

BE-S1000 Microprocessor Preliminary Datasheet

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1 Introduction

The BE-S1000 microprocessor is a *System-on-a-Chip (SoC)* for general purpose servers that require high performance, low power consumption, and multiple PCIe Gen4 interfaces with extensive customization options. It complies with [Arm® Server Base System Architecture](#), IPMI, ACPI, and UEFI specifications.

The SoC implements 48 Arm Cortex™-A75 cores. Each core operates at 2 GHz and supports L1, L2, L3, and L4 coherent caches.

The BE-S1000 implements six independent DDR4-3200 memory channels and a wide range of peripheral interfaces: PCIe Gen4, 1 Gb Ethernet, USB 2.0, SPI, UART, GPIO, etc.

The SoC provides three PCIe Gen4 CCIX interfaces to build a multi-processor system up to four BE-S1000 microprocessors and with a joint L4 coherent cache.

The BE-S1000 complies with [Arm TrustZone® technology](#) and contains the capabilities necessary to build trusted systems.

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1.1 Main Features

Table 1-1 Main features

Feature	Description
Armv8-A (v8.2) Architecture	48 Arm Cortex-A75 cores operating at 2 GHz
	12 core clusters (4 cores and 2 MB L3 cache per cluster)
	64 KB L1 instruction cache, 64 KB L1 data cache, and 512 KB L2 cache per core
L4 Coherent Cache	32 MB L4 cache
External Memory Interface	Six 64-bit DRAM channels with support of DDR4-3200 and ECC
	Up to 768 GB per socket (128 GB per channel)
Multi-SoC Interconnect	Three CCIX interfaces x16, each lane operates with 16 Gb/s
High Speed Peripherals	80 PCIe lanes of PCIe Gen4 (48 lanes are shared with CCIX interfaces)
	USB 2.0 ULPI interface
	Two 1 Gb Ethernet RGMII interfaces
Low Speed Peripherals	Four peripheral timers
	GPIOx32
	Two UARTs
	QSPI
	Three I ² C/SMBus controllers
	Optionally: GPIOx16 or eSPI
	Optionally: GPIOx8 or QSPI
Optionally: GPIOx8 or I ² C/SMBus + I ² C/SMBus + UART	
Security	Arm TrustZone architecture
	Secure boot
System Monitoring and Debug	24 PVT sensor blocks
	Watchdog timer
	Arm CoreSight™ debug and trace architecture
Package	FCLGA-3467 58x75.5 mm, 0.50 mm pitch, 3467 pins
Power Consumption	120 W
Operating Temperature	From 0 to +70°C
Technology	TSMC 16FFC

NOTE: The features in the table above are subject to change without notice.

1.2 Block Diagram

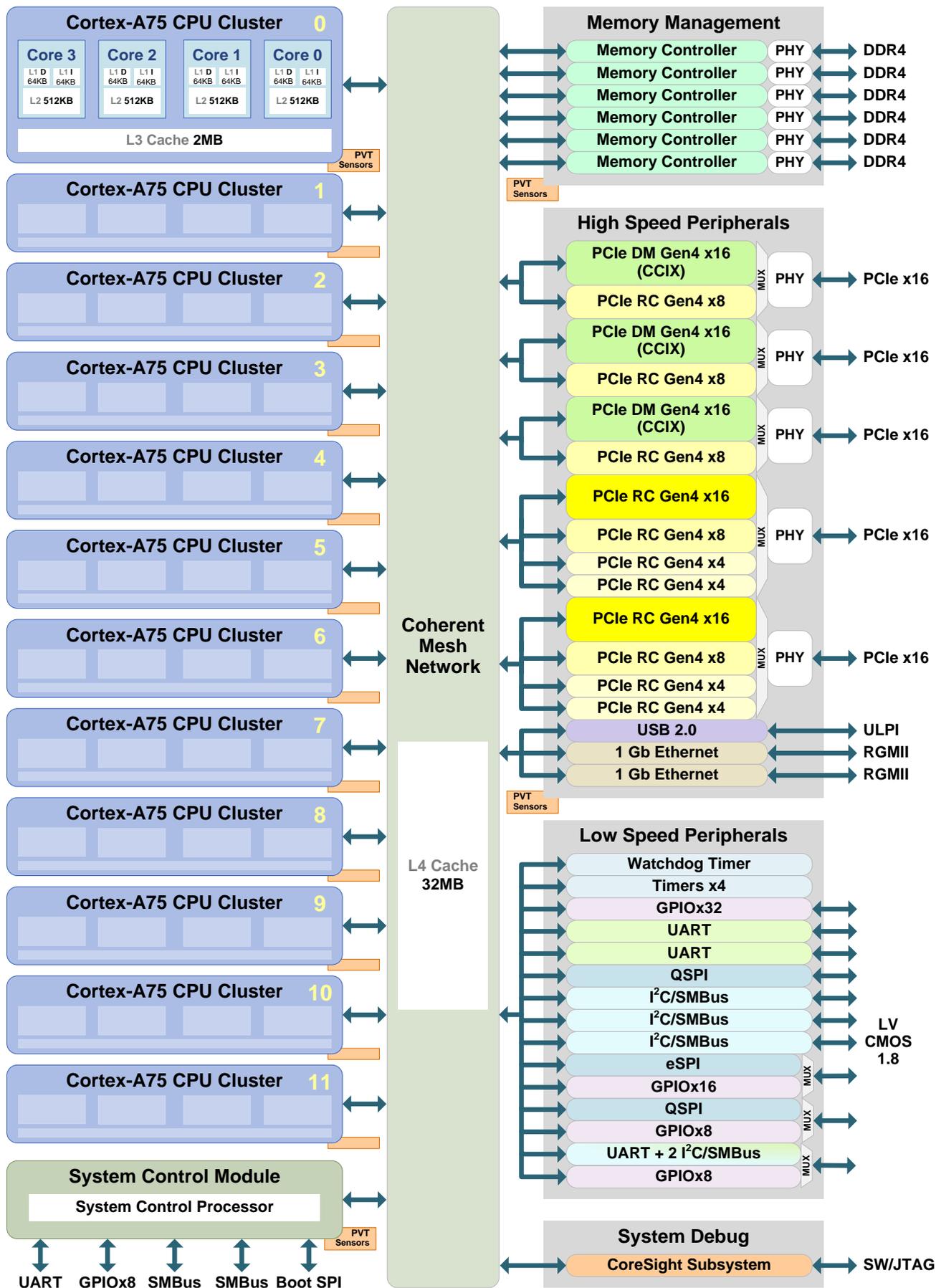


Figure 1-1 Block diagram

2 Detailed Description

2.1 Arm Cortex-A75 CPU Cluster

The SoC contains 48 Arm Cortex-A75 cores in 12 clusters.

Each cluster contains four cores (2 GHz) and L3 (2 MB) cache. Arm Cortex-A75 implements the [Armv8-A \(v8.2\) architecture](#).

Each core contains 512 KB L2 cache, 64 KB L1 instruction cache, and 64 KB L1 data cache.

A core supports the following ISA extensions:

- CRC32
- SQRDMLAH and SQRDMLSH
- UDOT and SDOT
- LDADD, LDCLR, LDEOR, LDSET, LDSMAX, LDSMIN, LDUMAX, LDUMIN, CAS, CASP, and SWP
- DC CVAP
- DAPRB, LDAPRH, and LDAPR

None of the cores in the clusters include optional Arm Cortex-A75 core Cryptographic Extension.

A core can operate in one of two possible states, known as the secure and non-secure. By propagating the security state of the core through the on-chip interconnect to target-based transaction filters, the TrustZone technology is extended through the SoC architecture, creating a robust platform supporting fully isolated trusted and non-trusted worlds.

2.2 DDR4 Memory Subsystem

The BE-S1000 provides six memory channels. Each channel includes DDR4 memory controller and integrated *Physical Layer (PHY)*, as shown in the following figure.

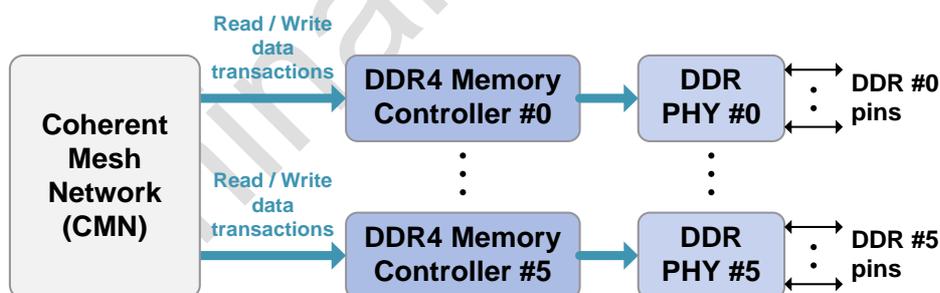


Figure 2-1 DDR4 memory subsystem diagram

Each memory channel supports:

- Up to 128 GB physical memory per channel
- 64-bit DDR4 (speed grades up to DDR4-3200)
- Integrated PHY
- Up to 4 memory ranks
- 1:2 frequency ratio mode
- 44-bit application address width
- 256-bit datawidth
- *Error Correction Code (ECC): Single Error Correction/Double Error Detection (SEC/DED)*

- DDR4U and DDR4L
- Industry standard UDIMMs and RDIMMs
- Low area, low power architecture
- Programmable support for 1T/2T memory command timing
- Software programmable *Quality of Service (QoS)*
- Automatic DDR4 low power mode operation
- Integrated [PVT Controller](#)

2.3 Coherent Mesh Network

Coherent Mesh Network (CMN) is based on the Arm CoreLink™ CMN-600. The CMN provides interconnection of the BE-S1000 macro-modules, manages the Level 4 coherent cache, and maps the global memory address space.

High-performance distributed system level cache (32 MB) includes an integrated *Point-of-Serialization (PoS)*, *Point-of-Coherency (PoC)*, and its **SLC** (also referred to as *Agile System Cache*), can be used both for compute and *Input/Output (I/O)* caching.

The CMN provides the following key features:

- 6×6 mesh network topology
- Pair of 256-bit data channels, one for each direction
- High-performance distributed SLC and *Snoop Filter (SF)*
- DVM message transport between masters
- Programmable *System Address Map (SAM)*
- RAS features including transport parity, optional data path parity, SEC/DED, ECC, and data poisoning signaling
- Supports [CCIX links for coherent communication](#)
- QoS regulation for shaping traffic profiles
- Performance monitoring events
- Separate caches for secure and non-secure transactions

2.4 System Control Module

This module is used to manage all the SoC subsystems.

It contains the following main blocks:

- *System Control Processor (SCP)* supports the following service functions:
 - The SoC startup
 - Initial configuration of all the SoC modules
 - SoC's state monitoring
- Boot SPI controller for initial boot
- UART, GPIOx8, and two I²C/SMBus interfaces used for system control functions

NOTE: These interfaces are under SCP control and are not available for Arm Cortex A-75 cores. The interfaces can be used if they have special support from the SDK.

2.5 High Speed Peripherals

BE-S1000 provides the following types of high speed interfaces:

- [PCIe interfaces](#)
- [USB 2.0](#)
- [1 Gb Ethernet](#)

2.5.1 PCIe Interfaces

BE-S1000 provides 80 PCIe lanes of PCIe Gen4 that are shared out for three [PCIe DM x16 Gen4](#) controllers and eleven [PCIe RC Gen4](#) controllers.

The PCIe controllers are combined into five *Macro-Modules (MM)*. Each MM is connected to the [Coherent Mesh Network](#) and supports 16 physical interface lanes through four integrated PCIe PHYs x4.

The following figure shows main functional subsystems of each PCIe MM.

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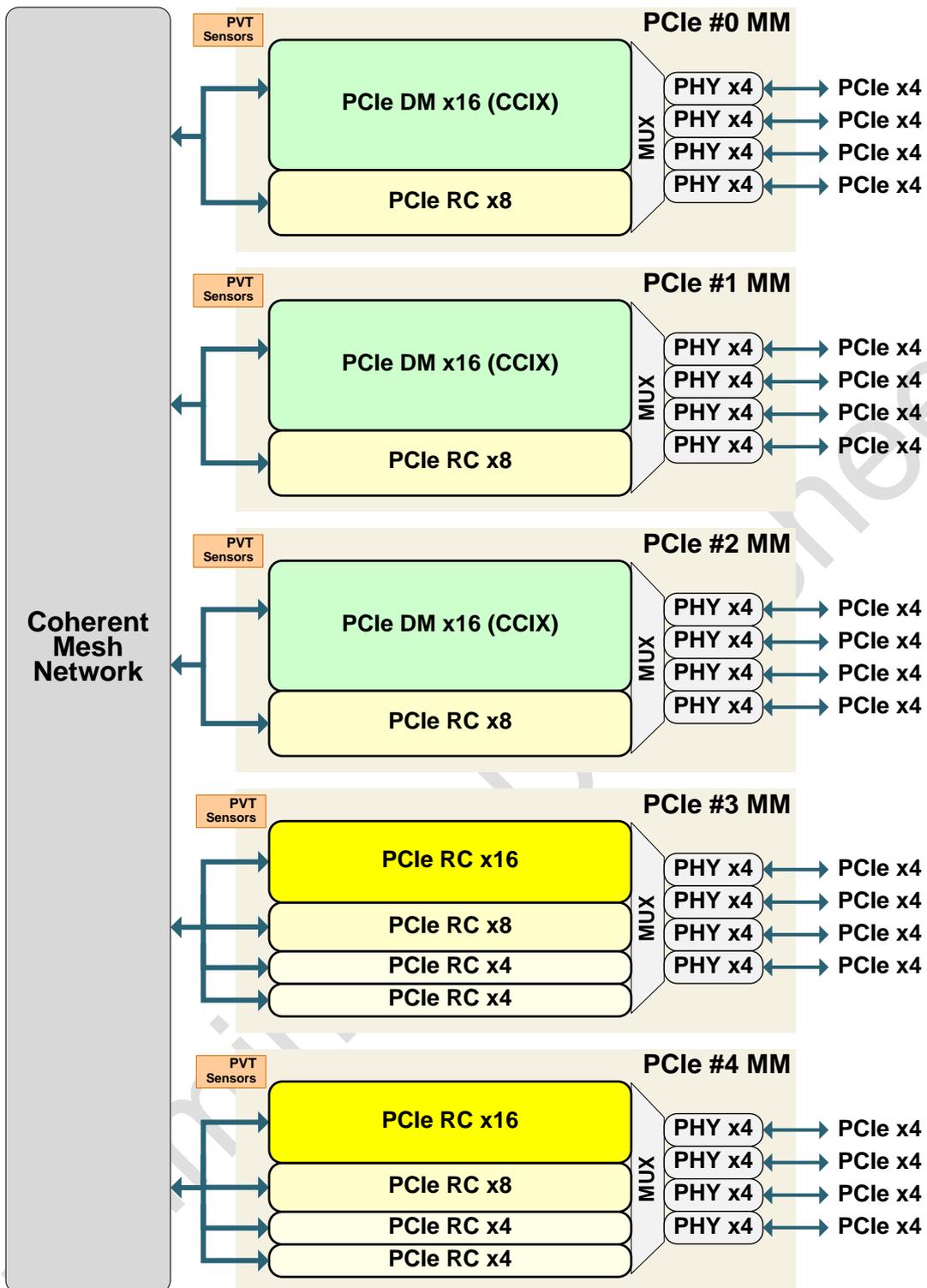


Figure 2-2 PCIe macro-modules

As the figure above shows, PCIe controllers of each macro-module can operate through up to 16 lanes. Each PCIe MM contains software controlled registers to provide the multiplexing function of PCIe PHYs.

NOTE: For details on how to control multiplexing PCIe PHYs, refer to section 5 *LCRU Implementations in Macro-Modules* in *BE-S1000 PROGRAMMING GUIDE Vol.6.1 System Monitoring and Management. Local Clock and Reset Unit (LCRU)*.

The following table shows possible PCIe layouts in BE-S1000.

Table 2-1 Possible PCIe layouts

PHY	Option	Controller	Operational mode	Lane count
PCIe x16 #0, #1, or #2	1	PCIe DM x16 (CCIX)	PCIe CCIX x16	16
		PCIe RC x8	not used	0
	2	PCIe DM x16 (CCIX)	PCIe RC x16	16
		PCIe RC x8	not used	0
	3	PCIe DM x16 (CCIX)	PCIe EP x16	16
		PCIe RC x8	not used	0
	4	PCIe DM x16 (CCIX)	PCIe RC x8	8
		PCIe RC x8	PCIe RC x8	8
	5	PCIe DM x16 (CCIX)	PCIe EP x8	8
		PCIe RC x8	PCIe RC x8	8
PCIe x16 #3 or #4	1	PCIe RC x16	PCIe RC x16	16
		PCIe RC x8	not used	0
		PCIe RC x4	not used	0
		PCIe RC x4	not used	0
	2	PCIe RC x16	PCIe RC x8	8
		PCIe RC x8	PCIe RC x8	8
		PCIe RC x4	not used	0
		PCIe RC x4	not used	0
	3	PCIe RC x16	PCIe RC x8	8
		PCIe RC x8	not used	0
		PCIe RC x4	PCIe RC x4	4
		PCIe RC x4	PCIe RC x4	4
	4	PCIe RC x16	not used	0
		PCIe RC x8	PCIe RC x8	8
		PCIe RC x4	PCIe RC x4	4
		PCIe RC x4	PCIe RC x4	4
	5	PCIe RC x16	PCIe RC x4	4
		PCIe RC x8	PCIe RC x4	4
		PCIe RC x4	PCIe RC x4	4
		PCIe RC x4	PCIe RC x4	4

2.5.1.1 PCIe RC Gen4

The SoC contains eleven PCIe *Root Complex (RC)* Gen4 subsystems:

- Two PCIe x16
- Five PCIe x8
- Four PCIe x4

Each PCIe RC subsystem contains PCIe controller, PCS, and integrated PHY. The controller supports all non-optional features of the **PCI Express Base Specification, Revision 4.0, Version 1.0**.

Each PCIe RC subsystem provides the following main features:

- Up to 16.0 GT/s (~ 2 GB/s) per single lane

- PCIe *Active State Power Management (ASPM)*
- PCIe *Advanced Error Reporting (AER)* with multiple header logging
- *Internal Address Translation Unit (IATU)*
- Embedded multichannel DMA controller
- Automatic lane reversal
- ECRC generation and checking
- Quality of service
- Virtual channels:
 - 1 channel for PCIe x4
 - 2 channels for PCIe x8
 - 3 channels for PCIe x16
- Maximum payload size:
 - 256 bytes for PCIe x4
 - 512 bytes for PCIe x8
 - 512 bytes for PCIe x16

Each subsystem can work both in secure and non-secure modes.

2.5.1.2 PCIe DM x16 Gen4

The SoC contains three PCIe *Dual Mode (DM)* x16 Gen4 subsystems.

Each PCIe DM subsystem contains PCIe controller, PCS, and integrated PHY. The controller supports all non-optional features of the **PCI Express Base Specification, Revision 4.0, Version 1.0**.

Each PCIe DM subsystem supports the following main features:

- Transfer rates up to 16.0 GT/s (~ 2 GB/s) per single lane
- [CCIX transport protocol](#)
- Optimized CCIX TLP interface
- Embedded CXS controller that supports *Coherent Multichip Link (CML)*
- PCIe *Active State Power Management (ASPM)*
- PCIe *Advanced Error Reporting (AER)* with multiple header logging
- *Internal Address Translation Unit (IATU)*
- Embedded multichannel DMA controller
- Automatic lane reversal
- ECRC generation and checking
- Integrated MSI reception module
- Quality of service
- 2 virtual channels
- Maximum payload size 1024 bytes

The subsystem provides capability of building a multi-socket system with up to four BE-S1000 microprocessors and a joint coherent cache L4. For more details, see [Multi-socket Systems](#).

Each subsystem can work both in secure and non-secure modes.

2.5.1.3 Multi-socket Systems

BE-S1000 contains three PCIe DM Gen4 subsystems that provide capability of building a multi-processor system with up to four BE-S1000 microprocessors and a joint coherent cache L4.

Each PCIe DM Gen4 subsystem supports CCIX Transport Protocol and contains embedded CXS controller that supports *Coherent Multichip Link (CML)*.

The following diagram shows an example of PCIe CCIX subsystem configuration that can be used to build a two-socket *Printed Circuit Board (PCB)*.

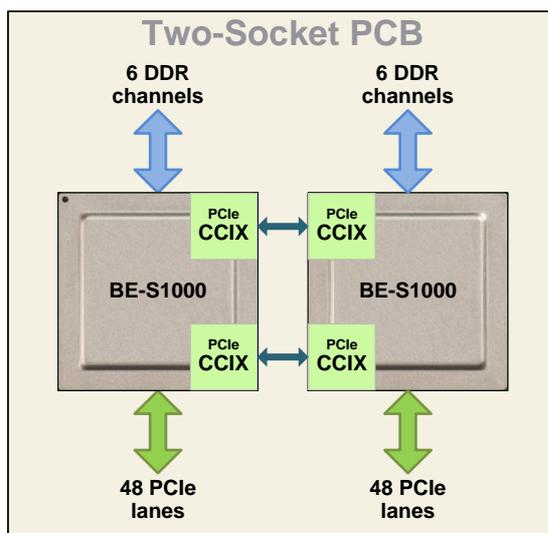


Figure 2-3 Two-socket BE-S1000 system on a PCB

The following diagram shows an example of PCIe CCIX subsystem configuration that can be used to build a four-socket PCB.

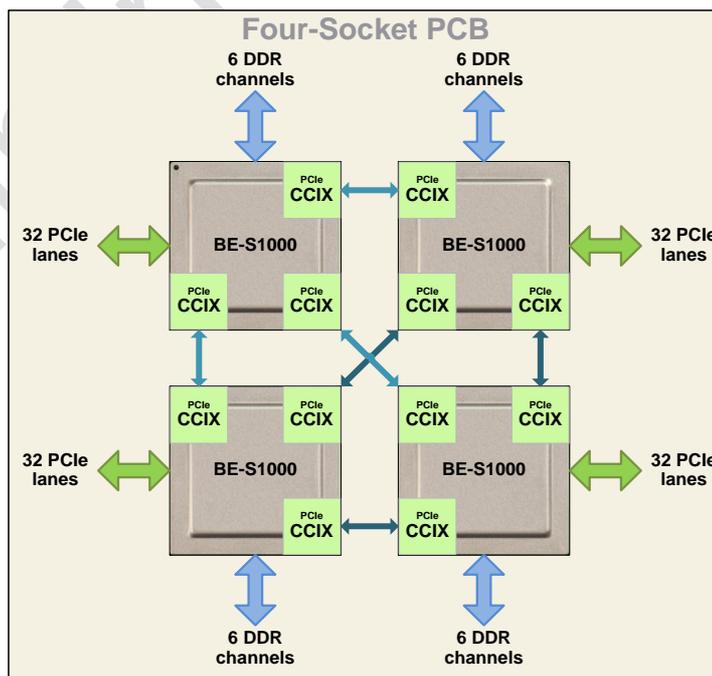


Figure 2-4 Four-socket BE-S1000 system on a PCB

2.5.2 USB 2.0

The USB 2.0 controller is compatible with the **xHCI Specification** by Intel Corporation. The output interface is compliant with **UTMI+ Low Pin Interface (ULPI) Specification**.

The controller contains one port optimized for high-bandwidth applications. It supports the following device types:

- High-Speed up to 480 Mbps
- Full-Speed up to 12 Mbps
- Low-Speed up to 1.5 Mbps

It can work both in secure and non-secure modes.

2.5.3 1 Gb Ethernet

There are two identical *1 Gigabit Media Access Controllers (GMAC)* in the SoC.

Each controller enables a host to transmit and receive data over Ethernet in compliance with the IEEE 802.3-2008 standard.

GMAC provides the following main features:

- RGMII interface
- 10, 100, and 1000 Mbps modes
- Full-duplex and half-duplex operation support
- Embedded DMA controller with independent transmit and receive engines

Each controller can work both in secure and non-secure modes.

2.6 Low Speed Peripherals

The BE-S1000 *Low Speed Peripherals (LSP)* subsystem contains [Watchdog Timer](#) and four peripheral [Timers](#) and the following interfaces:

- General purpose input/output ([GPIO](#)) with up to 32, 16, 8, and 8 bits of I/O
- Up to 2 universal asynchronous receivers/transmitters ([UART](#))
- Up to 2 quad serial peripheral interfaces ([QSPI](#))
- Enhanced Serial Peripheral Interface ([eSPI](#))
- Up to 5 inter-integrated circuits/system management bus controller ([I²C/SMBus](#))

The subsystem is connected to the [Coherent Mesh Network](#) and can operate under control of application processor (a core of Arm Cortex-A75 clusters) or SCP.

The following diagram shows main controllers of the LSP subsystem.

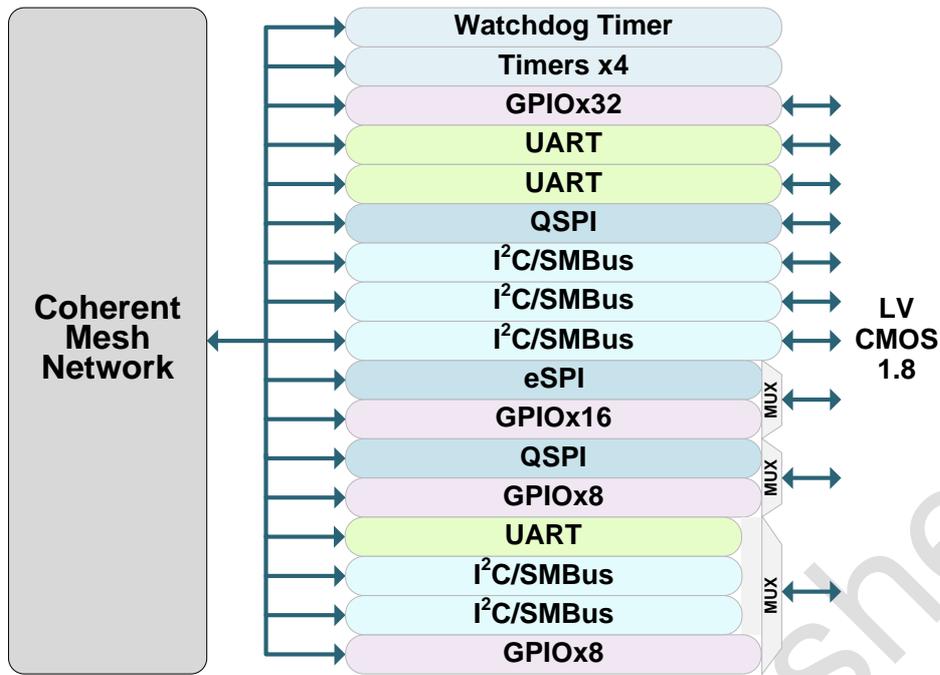


Figure 2-5 Low speed peripherals

As the figure above shows, some LSP controllers share physical interfaces: 32 pins of the SoC can be used for eight LSPs.

LSP subsystem contains software controlled registers to provide the function of multiplexing physical interfaces.

As shown in the following figure, System Control Module contains programmable register, used to control the LSP interface multiplexer.

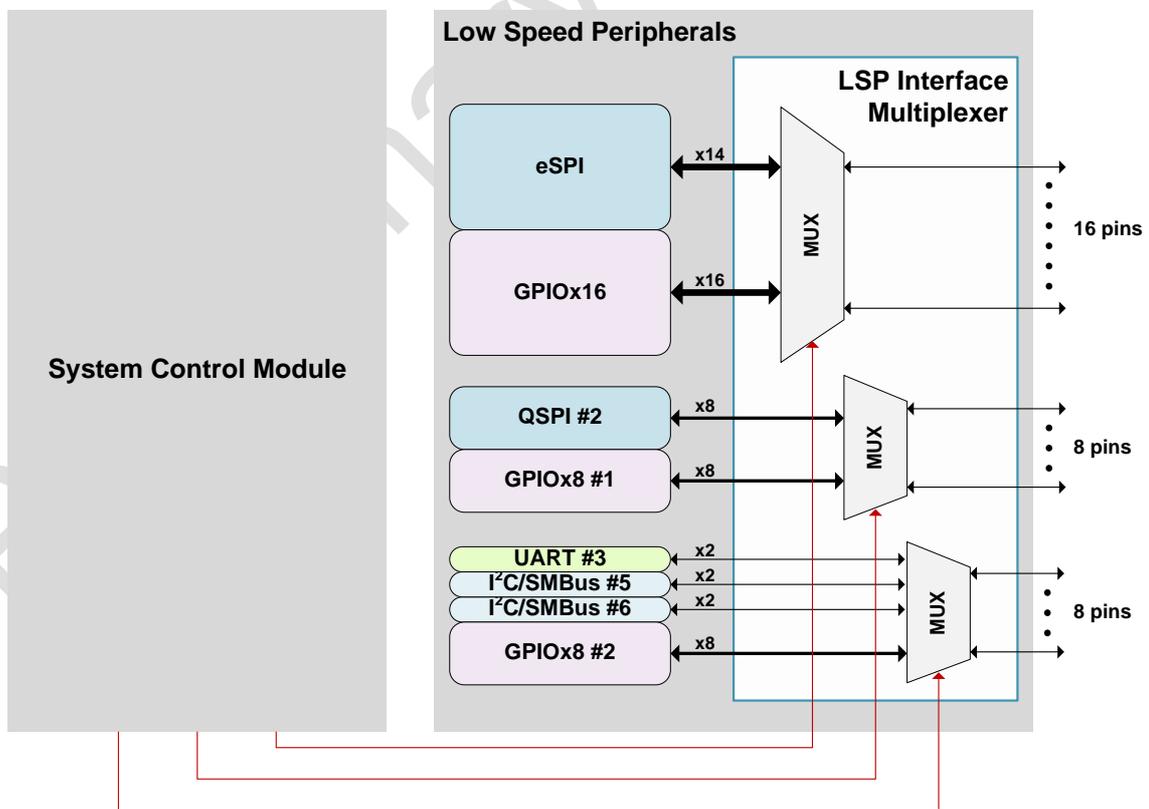


Figure 2-6 LSP multiplexing control

NOTE: For detailed LSP configuration description, refer to section **5.6 SC MM LCRU** in **BE-S1000 PROGRAMMING GUIDE Vol.6.1 System Monitoring and Management. Local Clock and Reset Unit (LCRU)**.

The following table shows possible LSP layouts in BE-S1000.

Table 2-2 Possible layouts for LSP

Pin port	Option	Interface	Pin count
x16	1	eSPI (SSx2)	14
		GPIO x16	not used
	2	eSPI (SSx2)	not used
		GPIO x16	16
x8	1	QSPI (SSx4)	8
		GPIO x8	not used
	2	QSPI (SSx4)	not used
		GPIO x8	8
x8	1	I ² C/SMBus	2
		I ² C/SMBus	2
		UART	2
		GPIO x8	not used
	2	I ² C/SMBus	not used
		I ² C/SMBus	not used
		UART	not used
		GPIO x8	8

2.6.1 GPIO

The SoC provides up to 64 individually programmable *General Purpose Input/Output (GPIO)* pins.

The SoC contains four GPIO controllers that support correspondently up to 32, 16, 8, and 8 bits of I/O. For details on possible GPIO pin configurations, see corresponding table in [Low Speed Peripherals](#).

Each GPIO controller controls the direction of data, data transactions, and interrupts on external pads using memory-mapped registers.

2.6.2 UART

There are three *Universal Asynchronous Receivers/Transmitters (UART)* in the SoC.

The first UART operates only in secure mode, the second one operates only in non-secure mode. The use of the third one is optional, it depends on LSP interface multiplexer. For details, see corresponding table in [Low Speed Peripherals](#).

An UART contains registers that control:

- Character length
- Baud rates up to 1.5 Mbaud
- Parity generation/checking
- Interrupt generation

2.6.3 QSPI

There are two *Quad Serial Peripheral Interface (QSPI)* controllers in the SoC.

The QSPI controller is a full-duplex master synchronous serial interface used for short distance communication with up to two external slave SPI devices (SSx2). It supports Single/Dual/Quad SPI mode of operation.

A master (a core or DMA controller) accesses data, control, and status information on the QSPI controller through the APB interface.

The QSPI controller can connect to a serial-slave peripheral device using **Motorola SPI interface**.

2.6.4 eSPI

The *Enhanced Serial Peripheral Interface (eSPI)* is a synchronous serial communication interface used for short distance communication.

Additional eSPI signals in comparison with SPI Interface:

- RESET programmable as input or output
- ALERT input interrupts

eSPI device communicates in full-duplex mode using master-slave architecture with up to four external slave SPI devices (SSx4). It supports single/dual/quad SPI mode of operation.

For details on how to use the eSPI, see corresponding table in [Low Speed Peripherals](#).

2.6.5 I²C/SMBus

The *Inter-Integrated Circuits/System Management Bus (I²C/SMBus)* is a two-wire interface through which various system components can communicate with each other and with the rest of the system. It is based on the principles of operation of the I²C bus.

The SoC includes five I²C/SMBus controllers:

- Three I²C/SMBus controllers support the ALERT and SUSPEND signals and have dedicated pins
- Two I²C/SMBus controllers do not support the ALERT and SUSPEND signals and can be connected to pinout, as described in corresponding table in [Low Speed Peripherals](#)

2.6.6 Timers

The module contains four independent peripheral timers.

Each peripheral timer is a 32-bit programmable timer supporting “free-running” and “user-defined count” modes.

In “user-defined count” mode, a timer counts down from a programmed value and generates an interrupt when the count reaches zero. Timer interrupt can be detected even when the system bus clock is stopped.

2.7 System Monitoring and Debug

2.7.1 Process, Voltage, and Temperature (PVT) Sensors

The SoC contains twenty four identical PVT sensor blocks used to monitor process, voltage, and temperature in CPU clusters, memory channels, PCIe subsystems, and the system control module.

Each PVT sensor blocks provides the following features:

- Measurement readiness is determined by polling data register or listening the interrupt line
- Programmable upper and lower threshold values for the measured PVT parameters to produce out-of-range interrupts
- Programmable timeout value for repetitive PVT parameters monitoring

2.7.2 Watchdog Timer

Watchdog Timer (WDT) is used to prevent system lockup that may be caused by software errors or hardware conflicts.

If a timeout occurs, the WDT can perform one of the following operations:

- Generates a system reset
- Firstly it generates an interrupt and waits the interrupt is cleared until a second timeout and then generates a system reset

The generated interrupt is passed to the *Generic Interrupt Controller (GIC)*. The generated reset is passed to the SCM, which in turn generates a reset for the components in the system. The WDT may be reset independently of other subsystems.

2.7.3 CoreSight Subsystem

The CoreSight subsystem provides a standard implementation of the Arm Debug Interface for debug tools to work with *Serial Wire or JTAG (SW/JTAG)* debug port.

The subsystem supports the following methods of debugging the SoC:

- “External” debug – conventional debug through the SW/JTAG interface
- “Self-hosted” debug – conventional debug with the processor running using a debug monitor that resides in memory
- Logging of hardware and software events in a trace, recorded in memory

It can work both in secure and non-secure modes.

3 Electrical Specifications

NOTE: The power supply parameters and reference clock requirements are subject to change without notice.

3.1 Power Supply Parameters

BE-S1000 requires six isolated voltage supplies and single unified ground supply, as shown in the following table.

Table 3-1 BE-S1000 power domains

Supply type	Pin name	Voltage, V	Max power, W
Core supply	VDD	$0.9 \pm 10\%$	81
0.85V voltage supply	VDD_PCIE0_VP VDD_PCIE1_VP VDD_PCIE2_VP VDD_PCIE3_VP VDD_PCIE4_VP	$0.85 \pm 10\%$	8.5
PLL supply	VDD_PLL	$1.8 \pm 10\%$	0.27
DDR supply	VDDQ012 VDDQ345	$1.2 \pm 10\%$	12
DDR PLL supply	VDD_DDR_PLL	$1.8 \pm 10\%$	0.09
1.8V voltage supply	VDD_PCIE0_VPH VDD_PCIE1_VPH VDD_PCIE2_VPH VDD_PCIE3_VPH VDD_PCIE4_VPH VDD_PVT VDDIO	$1.8 \pm 10\%$	18
Ground	VSS VSSIO	$0 \pm 10\%$	0
Total			~120

3.2 External Clocking

3.2.1 Reference Clock Signals

Table 3-2 Reference clock signals

Clock signal	Pin name	Frequency, MHz
Reference clock	REFCLK	25 or 100
PCIe PHY reference clock	PCIEn_CLKm_DN* PCIEn_CLKm_DP*	100

* n – number of PCIe MM, m – number of PCIe PHY. For details, refer to [PCIe Interfaces](#).

3.2.2 Reference Clock Requirements

3.2.2.1 Reference Clock

Table 3-3 Reference clock requirements

Parameter	Min	Typ	Max	Unit
Input frequency	-	25 or 100*	-	MHz
Duty cycle	45	-	55	%
Lock time	-	-	70	us
Reset time	1	-	-	us

* The REFCLK_SEL signal level must correspond to frequency value of reference clock. For details, refer to the corresponding [Pin Description](#).

3.2.2.2 PCIe PHY Reference Clock

Each PCIe subsystem contains four PCIe x4 PHYs. The PHYs require input reference clock signals, as shown in the following figure.

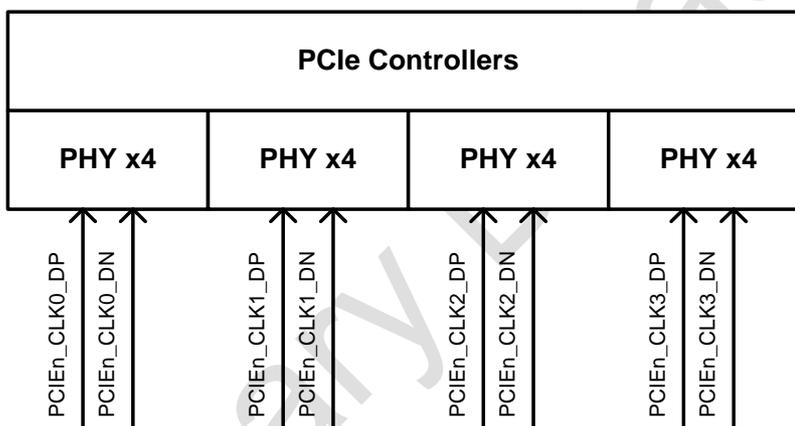


Figure 3-1 PCIe PHY reference clock diagram

The following table describes reference clock requirements for a PCIe PHY.

Table 3-4 PCIe PHY reference clock requirements

Parameter	Min	Typ	Max	Unit
Input frequency	-	100	-	MHz
Rising edge rate	0.6	-	4.0	V/ns
Falling edge rate	0.6	-	4.0	V/ns
Average clock period accuracy	-300	-	2800	ppm
Cycle to cycle jitter	-	-	150	ps
Duty cycle	40	-	60	%
Rise-fall matching	-	20	-	%
Clock source DC impedance	40	-	60	Ohms

4 Power-Up/Down

4.1 Power-Up Sequence

The power-up sequence of power domains have to match the following recommendations. Any deviation from the following norms may cause:

- Overcurrent at start
- Incorrect device load
- Device damage

Requirements for the power-up:

1. Power domains must be enable when `RESET_N`, `CS_TRST_N`, `PCIEx_PERST_N` and `TRST_N` signals are active (active is low).
2. Supply power-up ramp rate for `VDDQx` and `VDD_DDR_PLL` is 5 mV/us max.
3. Supply ramp for others domains should be monotonic with a ramp time of no faster than 10 us and a rate no faster than (supply voltage)/10 us.
4. After 100 cycles of `REFCLK` reference clock (25 MHz), `RESET_N` signal must be high. `CS_TRST_N` and `TRST_N` signals must be high simultaneously with `RESET_N`.
5. Before 15 ms then `RESET_N` signal is high, `PCIEx_PERST_N` signals must be high.

The following figure shows the power-up sequence for BE-S1000.

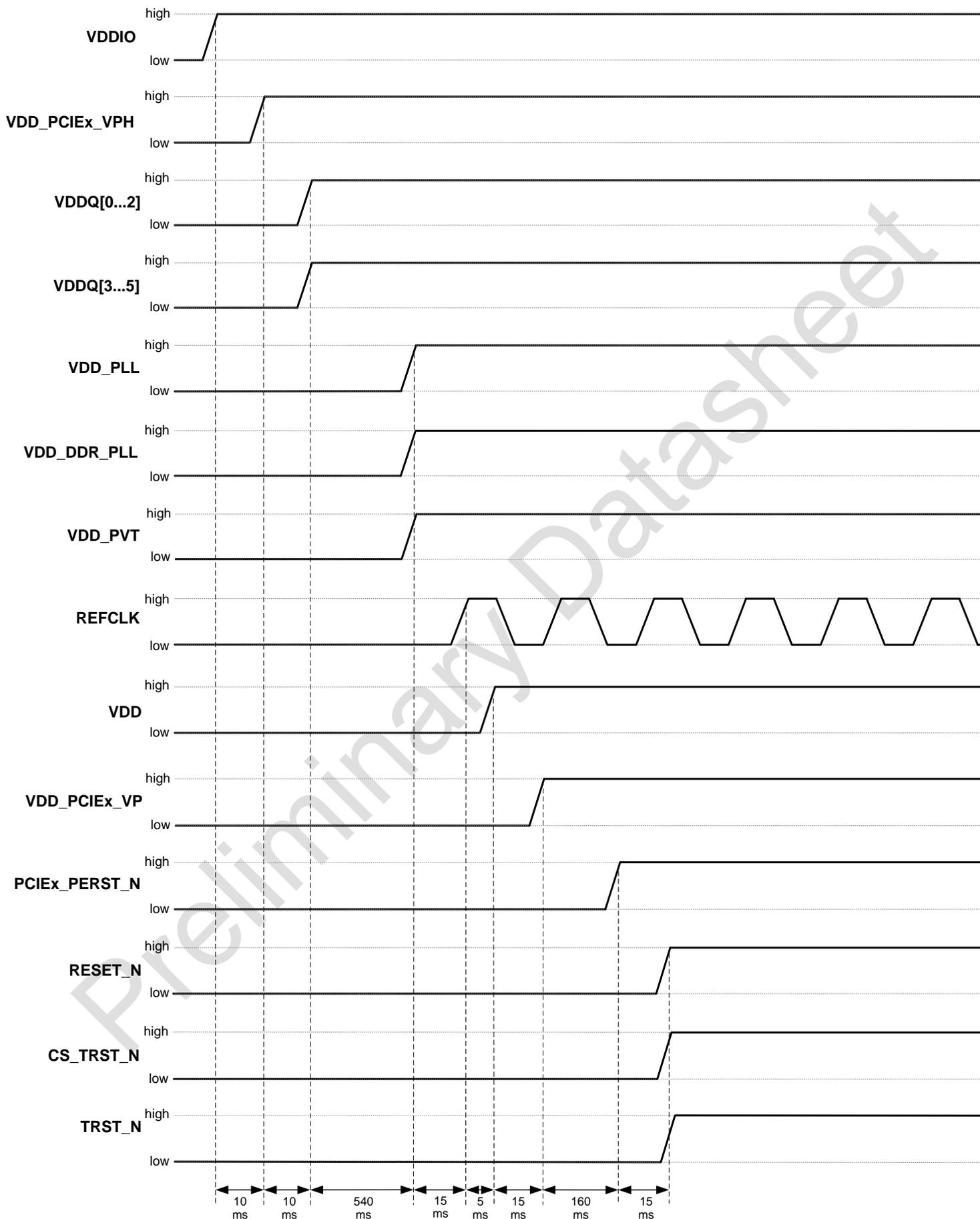


Figure 4-1 Power-up sequence diagram for the BE-S1000

4.2 Power-Down Sequence

Power-down must be done in reverse sequence given in [4.1 Power-Up Sequence](#)

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5 Pin Assignment

5.1 Pinout List

The following tables contain the list of I/O pins of the SoC including the power supply and ground pins. The following legend is applied for the following tables.

Legend:

I	Input
O	Output
IO	Input/Output
A	Analog
P	Power supply
G	Ground
NC	Not connected

5.1.1 DDR4

5.1.1.1 DDR #0

Table 5-1 DDR #0 pins

Pin name	Type	Description
DDR0_A[13:0]	O	SDRAM address
DDR0_A[14]	O	WE_N write enable
DDR0_A[15]	O	CAS_N column address strobe bus
DDR0_A[16]	O	RAS_N row address strobe bus
DDR0_A[17]	O	SDRAM address
DDR0_ACT_N	O	ACT_N activation command
DDR0_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR0_BA[1:0]	O	SDRAM bank address
DDR0_BG[1:0]	O	SDRAM bank group
DDR0_CKE[3:0]	O	SDRAM clock enable
DDR0_CLK_DN[3:0]	O	CLK0_C...CLK3_C SDRAM clock
DDR0_CLK_DP[3:0]	O	CLK0_T...CLK3_T SDRAM clock
DDR0_CS_N[3:0]	O	SDRAM chip select
DDR0_DQ[63:0]	IO	SDRAM data
DDR0_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR0_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR0_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte
DDR0_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR0_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR0_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p

Pin name	Type	Description
DDR0_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR0_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR0_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR0_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR0_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR0.DTO	O	Primary digital observation
DDR0_ECC[7:0]	IO	SDRAM data ECC
DDR0_ODT[3:0]	O	SDRAM on-die termination
DDR0_PAR	O	SDRAM parity value for DFI command
DDR0_RESET_N	O	SDRAM reset
DDR0_VREF	A	Reference voltage
DDR0_ZN	A	Calibration resistor connection

5.1.1.2 DDR #1

Table 5-2 DDR #1 pins

Pin name	Type	Description
DDR1_A[13:0]	O	SDRAM address
DDR1_A[14]	O	WE_N write enable
DDR1_A[15]	O	CAS_N column address strobe bus
DDR1_A[16]	O	RAS_N row address strobe bus
DDR1_A[17]	O	SDRAM address
DDR1_ACT_N	O	ACT_N activation command
DDR1_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR1_BA[1:0]	O	SDRAM bank address
DDR1_BG[1:0]	O	SDRAM bank group
DDR1_CKE[3:0]	O	SDRAM clock enable
DDR1_CLK_DN[3:0]	O	CLK0_C...CLK3_C SDRAM clock
DDR1_CLK_DP[3:0]	O	CLK0_T...CLK3_T SDRAM clock
DDR1_CS_N[3:0]	O	SDRAM chip select
DDR1_DQ[63:0]	IO	SDRAM data
DDR1_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR1_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR1_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte

Pin name	Type	Description
DDR1_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR1_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR1_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p
DDR1_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR1_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR1_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR1_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR1_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR1.DTO	O	Primary digital observation
DDR1.ECC[7:0]	IO	SDRAM data ECC
DDR1.ODT[3:0]	O	SDRAM on-die termination
DDR1.PAR	O	SDRAM parity value for DFI command
DDR1.RESET_N	O	SDRAM reset
DDR1.VREF	A	Reference voltage
DDR1.ZN	A	Calibration resistor connection

5.1.1.3 DDR #2

Table 5-3 DDR #2 pins

Pin name	Type	Description
DDR2_A[13:0]	O	SDRAM address
DDR2_A[14]	O	WE_N write enable
DDR2_A[15]	O	CAS_N column address strobe bus
DDR2_A[16]	O	RAS_N row address strobe bus
DDR2_A[17]	O	SDRAM address
DDR2_ACT_N	O	ACT_N activation command
DDR2_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR2_BA[1:0]	O	SDRAM bank address
DDR2_BG[1:0]	O	SDRAM bank group
DDR2_CKE[3:0]	O	SDRAM clock enable
DDR2_CLK_DN[3:0]	O	CLK0_C...CLK3_C SDRAM clock
DDR2_CLK_DP[3:0]	O	CLK0_T...CLK3_T SDRAM clock
DDR2_CS_N[3:0]	O	SDRAM chip select
DDR2_DQ[63:0]	IO	SDRAM data

Pin name	Type	Description
DDR2_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR2_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR2_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte
DDR2_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR2_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR2_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p
DDR2_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR2_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR2_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR2_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR2_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR2_DTO	O	Primary digital observation
DDR2_ECC[7:0]	IO	SDRAM data ECC
DDR2_ODT[3:0]	O	SDRAM on-die termination
DDR2_PAR	O	SDRAM parity value for DFI command
DDR2_RESET_N	O	SDRAM reset
DDR2_VREF	A	Reference voltage
DDR2_ZN	A	Calibration resistor connection

5.1.1.4 DDR #3

Table 5-4 DDR #3 pins

Pin name	Type	Description
DDR3_A[13:0]	O	SDRAM address
DDR3_A[14]	O	WE_N write enable
DDR3_A[15]	O	CAS_N column address strobe bus
DDR3_A[16]	O	RAS_N row address strobe bus
DDR3_A[17]	O	SDRAM address
DDR3_ACT_N	O	ACT_N activation command
DDR3_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR3_BA[1:0]	O	SDRAM bank address
DDR3_BG[1:0]	O	SDRAM bank group
DDR3_CKE[3:0]	O	SDRAM clock enable

Pin name	Type	Description
DDR3_CLK_DN[0]	O	CLK0_C...CLK3_C SDRAM clock
DDR3_CLK_DP[0]	O	CLK0_T...CLK3_T SDRAM clock
DDR3_CS_N[3:0]	O	SDRAM chip select
DDR3_DQ[63:0]	IO	SDRAM data
DDR3_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR3_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR3_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte
DDR3_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR3_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR3_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p
DDR3_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR3_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR3_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR3_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR3_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR3.DTO	O	Primary digital observation
DDR3.ECC[7:0]	IO	SDRAM data ECC
DDR3.ODT[3:0]	O	SDRAM on-die termination
DDR3.PAR	O	SDRAM parity value for DFI command
DDR3.RESET_N	O	SDRAM reset
DDR3.VREF	A	Reference voltage
DDR3.ZN	A	Calibration resistor connection

5.1.1.5 DDR #4

Table 5-5 DDR #4 pins

Pin name	Type	Description
DDR4_A[13:0]	O	SDRAM address
DDR4_A[14]	O	WE_N write enable
DDR4_A[15]	O	CAS_N column address strobe bus
DDR4_A[16]	O	RAS_N row address strobe bus
DDR4_A[17]	O	SDRAM address
DDR4_ACT_N	O	ACT_N activation command

Pin name	Type	Description
DDR4_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR4_BA[1:0]	O	SDRAM bank address
DDR4_BG[1:0]	O	SDRAM bank group
DDR4_CKE[3:0]	O	SDRAM clock enable
DDR4_CLK_DN[3:0]	O	CLK0_C...CLK3_C SDRAM clock
DDR4_CLK_DP[3:0]	O	CLK0_T...CLK3_T SDRAM clock
DDR4_CS_N[3:0]	O	SDRAM chip select
DDR4_DQ[63:0]	IO	SDRAM data
DDR4_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR4_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR4_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte
DDR4_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR4_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR4_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p
DDR4_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR4_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR4_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR4_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR4_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR4.DTO	O	Primary digital observation
DDR4_ECC[7:0]	IO	SDRAM data ECC
DDR4_ODT[3:0]	O	SDRAM on-die termination
DDR4_PAR	O	SDRAM parity value for DFI command
DDR4_RESET_N	O	SDRAM reset
DDR4_VREF	A	Reference voltage
DDR4_ZN	A	Calibration resistor connection

5.1.1.6 DDR #5

Table 5-6 DDR #5 pins

Pin name	Type	Description
DDR5_A[13:0]	O	SDRAM address
DDR5_A[14]	O	WE_N write enable

Pin name	Type	Description
DDR5_A[15]	O	CAS_N column address strobe bus
DDR5_A[16]	O	RAS_N row address strobe bus
DDR5_A[17]	O	SDRAM address
DDR5_ACT_N	O	ACT_N activation command
DDR5_ALERT_N	IO	CRC or parity error Indicates that a CRC or parity error has been detected for a previous command (active low)
DDR5_BA[1:0]	O	SDRAM bank address
DDR5_BG[1:0]	O	SDRAM bank group
DDR5_CKE[3:0]	O	SDRAM clock enable
DDR5_CLK_DN[3:0]	O	CLK0_C...CLK3_C SDRAM clock
DDR5_CLK_DP[3:0]	O	CLK0_T...CLK3_T SDRAM clock
DDR5_CS_N[3:0]	O	SDRAM chip select
DDR5_DQ[63:0]	IO	SDRAM data
DDR5_DQS_DN[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: LDQS_n
DDR5_DQS_DN[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: DQS_n for byte; x16 mode: UDQS_n
DDR5_DQS_DN[8]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: DQS_n for ECC byte; x16 mode: DQS_n for ECC byte
DDR5_DQS_DN[16:9]	IO	SDRAM data strobe. x4 mode: DQS_n for nibble; x8 mode: TDQS_n for byte; x16 mode: not used
DDR5_DQS_DN[17]	IO	SDRAM data strobe. x4 mode: DQS_n for ECC nibble; x8 mode: TDQS_n for ECC byte; x16 mode: not used
DDR5_DQS_DP[0,2,4,6]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: LDQS_p
DDR5_DQS_DP[1,3,5,7]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DQS_p for byte; x16 mode: UDQS_p
DDR5_DQS_DP[8]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DQS_p for ECC byte; x16 mode: DQS_p for ECC byte
DDR5_DQS_DP[9,11,13,15]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for LDQ
DDR5_DQS_DP[10,12,14,16]	IO	SDRAM data strobe. x4 mode: DQS_p for nibble; x8 mode: DM/DBI/TDQS_p; x16 mode: DM/DBI for UDQ
DDR5_DQS_DP[17]	IO	SDRAM data strobe. x4 mode: DQS_p for ECC nibble; x8 mode: DM/DBI/TDQS_p for ECC; x16 mode: DM/DBI for ECC
DDR5.DTO	O	Primary digital observation
DDR5_ECC[7:0]	IO	SDRAM data ECC
DDR5_ODT[3:0]	O	SDRAM on-die termination
DDR5_PAR	O	SDRAM parity value for DFI command
DDR5_RESET_N	O	SDRAM reset
DDR5_VREF	A	Reference voltage
DDR5_ZN	A	Calibration resistor connection

5.1.2 High Speed Peripherals

5.1.2.1 PCIe x16 #0

Table 5-7 PCIe x16 #0 pins

Pin name	Type	Description
PCIE0_ATT_BUT[1:0]	I	Sets whether the system attention button is pressed
PCIE0_ATT_IND[3:0]	O	Controls the system attention indicator
PCIE0_CLK0_DN	I	PCIe differential reference clock
PCIE0_CLK0_DP	I	PCIe differential reference clock
PCIE0_CLK1_DN	I	PCIe differential reference clock
PCIE0_CLK1_DP	I	PCIe differential reference clock
PCIE0_CLK2_DN	I	PCIe differential reference clock
PCIE0_CLK2_DP	I	PCIe differential reference clock
PCIE0_CLK3_DN	I	PCIe differential reference clock
PCIE0_CLK3_DP	I	PCIe differential reference clock
PCIE0_CMD_INT[1:0]	I	Hot-plug controller command completed interrupt
PCIE0_INTRL_CTRL[1:0]	O	Electromechanical interlock control
PCIE0_INTRL_ENG[1:0]	I	System electromechanical interlock engaged
PCIE0_MRL_SENS[1:0]	I	MRL sensor state
PCIE0_PERST_N[1:0]	I	PERST
PCIE0_PRES_ST[1:0]	I	Presence detect state
PCIE0_PWR_CTRL[1:0]	O	Controls the system power controller
PCIE0_PWR_FAULT[1:0]	I	Power fault detected
PCIE0_PWR_IND[3:0]	O	Controls the system power indicator
PCIE0_RESREF	A	Reference resistor connection
PCIE0_RX_DN[15:0]	I	PCIe differential receive pair
PCIE0_RX_DP[15:0]	I	PCIe differential receive pair
PCIE0_TX_DN[15:0]	O	PCIe differential transmit pair
PCIE0_TX_DP[15:0]	O	PCIe differential transmit pair

5.1.2.2 PCIe x16 #1

Table 5-8 PCIe x16 #1 pins

Pin name	Type	Description
PCIE1_ATT_BUT[1:0]	I	Sets whether the system attention button is pressed
PCIE1_ATT_IND[3:0]	O	Controls the system attention indicator
PCIE1_CLK0_DN	I	PCIe differential reference clock
PCIE1_CLK0_DP	I	PCIe differential reference clock
PCIE1_CLK1_DN	I	PCIe differential reference clock

Pin name	Type	Description
PCIE1_CLK1_DP	I	PCIe differential reference clock
PCIE1_CLK2_DN	I	PCIe differential reference clock
PCIE1_CLK2_DP	I	PCIe differential reference clock
PCIE1_CLK3_DN	I	PCIe differential reference clock
PCIE1_CLK3_DP	I	PCIe differential reference clock
PCIE1_CMD_INT[1:0]	I	Hot-plug controller command completed interrupt
PCIE1_INTRL_CTRL[1:0]	O	Electromechanical interlock control
PCIE1_INTRL_ENG[1:0]	I	System electromechanical interlock engaged
PCIE1_MRL_SENS[1:0]	I	MRL sensor state
PCIE1_PERST_N[1:0]	I	PERST
PCIE1_PRES_ST[1:0]	I	Presence detect state
PCIE1_PWR_CTRL[1:0]	O	Controls the system power controller
PCIE1_PWR_FAULT[1:0]	I	Power fault detected
PCIE1_PWR_IND[3:0]	O	Controls the system power indicator
PCIE1_RESREF	A	Reference resistor connection
PCIE1_RX_DN[15:0]	I	PCIe differential receive pair
PCIE1_RX_DP[15:0]	I	PCIe differential receive pair
PCIE1_TX_DN[15:0]	O	PCIe differential transmit pair
PCIE1_TX_DP[15:0]	O	PCIe differential transmit pair

5.1.2.3 PCIe x16 #2

Table 5-9 PCIe x16 #2 pins

Pin name	Type	Description
PCIE2_ATT_BUT[1:0]	I	Sets whether the system attention button is pressed
PCIE2_ATT_IND[3:0]	O	Controls the system attention indicator
PCIE2_CLK0_DN	I	PCIe differential reference clock
PCIE2_CLK0_DP	I	PCIe differential reference clock
PCIE2_CLK1_DN	I	PCIe differential reference clock
PCIE2_CLK1_DP	I	PCIe differential reference clock
PCIE2_CLK2_DN	I	PCIe differential reference clock
PCIE2_CLK2_DP	I	PCIe differential reference clock
PCIE2_CLK3_DN	I	PCIe differential reference clock
PCIE2_CLK3_DP	I	PCIe differential reference clock
PCIE2_CMD_INT[1:0]	I	Hot-plug controller command completed interrupt
PCIE2_INTRL_CTRL[1:0]	O	Electromechanical interlock control
PCIE2_INTRL_ENG[1:0]	I	System electromechanical interlock engaged

Pin name	Type	Description
PCIE2_MRL_SENS[1:0]	I	MRL sensor state
PCIE2_PERST_N[1:0]	I	PERST
PCIE2_PRES_ST[1:0]	I	Presence detect state
PCIE2_PWR_CTRL[1:0]	O	Controls the system power controller
PCIE2_PWR_FAULT[1:0]	I	Power fault detected
PCIE2_PWR_IND[3:0]	O	Controls the system power indicator
PCIE2_RESREF	A	Reference resistor connection
PCIE2_RX_DN[15:0]	I	PCIe differential receive pair
PCIE2_RX_DP[15:0]	I	PCIe differential receive pair
PCIE2_TX_DN[15:0]	O	PCIe differential transmit pair
PCIE2_TX_DP[15:0]	O	PCIe differential transmit pair

5.1.2.4 PCIe x16 #3

Table 5-10 PCIe x16 #3 pins

Pin name	Type	Description
PCIE3_ATT_BUT[3:0]	I	Sets whether the system attention button is pressed
PCIE3_ATT_IND[7:0]	O	Controls the system attention indicator
PCIE3_CLK0_DN	I	PCIe differential reference clock
PCIE3_CLK0_DP	I	PCIe differential reference clock
PCIE3_CLK1_DN	I	PCIe differential reference clock
PCIE3_CLK1_DP	I	PCIe differential reference clock
PCIE3_CLK2_DN	I	PCIe differential reference clock
PCIE3_CLK2_DP	I	PCIe differential reference clock
PCIE3_CLK3_DN	I	PCIe differential reference clock
PCIE3_CLK3_DP	I	PCIe differential reference clock
PCIE3_CMD_INT[3:0]	I	Hot-plug controller command completed interrupt
PCIE3_INTRL_CTRL[3:0]	O	Electromechanical interlock control
PCIE3_INTRL_ENG[3:0]	I	System electromechanical interlock engaged
PCIE3_MRL_SENS[3:0]	I	MRL sensor state
PCIE3_PERST_N[3:0]	I	PERST
PCIE3_PRES_ST[3:0]	I	Presence detect state
PCIE3_PWR_CTRL[3:0]	O	Controls the system power controller
PCIE3_PWR_FAULT[3:0]	I	Power fault detected
PCIE3_PWR_IND[7:0]	O	Controls the system power indicator
PCIE3_RESREF	A	Reference resistor connection
PCIE3_RX_DN[15:0]	I	PCIe differential receive pair

Pin name	Type	Description
PCIE3_RX_DP[15:0]	I	PCIe differential receive pair
PCIE3_TX_DN[15:0]	O	PCIe differential transmit pair
PCIE3_TX_DP[15:0]	O	PCIe differential transmit pair

5.1.2.5 PCIe x16 #4

Table 5-11 PCIe x16 #4 pins

Pin name	Type	Description
PCIE4_ATT_BUT[3:0]	I	Sets whether the system attention button is pressed
PCIE4_ATT_IND[7:0]	O	Controls the system attention indicator
PCIE4_CLK0_DN	I	PCIe differential reference clock
PCIE4_CLK0_DP	I	PCIe differential reference clock
PCIE4_CLK1_DN	I	PCIe differential reference clock
PCIE4_CLK1_DP	I	PCIe differential reference clock
PCIE4_CLK2_DN	I	PCIe differential reference clock
PCIE4_CLK2_DP	I	PCIe differential reference clock
PCIE4_CLK3_DN	I	PCIe differential reference clock
PCIE4_CLK3_DP	I	PCIe differential reference clock
PCIE4_CMD_INT[3:0]	I	Hot-plug controller command completed interrupt
PCIE4_INTRL_CTRL[3:0]	O	Electromechanical interlock control
PCIE4_INTRL_ENG[3:0]	I	System electromechanical interlock engaged
PCIE4_MRL_SENS[3:0]	I	MRL sensor state
PCIE4_PERST_N[3:0]	I	PERST
PCIE4_PRES_ST[3:0]	I	Presence detect state
PCIE4_PWR_CTRL[3:0]	O	Controls the system power controller
PCIE4_PWR_FAULT[3:0]	I	Power fault detected
PCIE4_PWR_IND[7:0]	O	Controls the system power indicator
PCIE4_RESREF	A	Reference resistor connection
PCIE4_RX_DN[15:0]	I	PCIe differential receive pair
PCIE4_RX_DP[15:0]	I	PCIe differential receive pair
PCIE4_TX_DN[15:0]	O	PCIe differential transmit pair
PCIE4_TX_DP[15:0]	O	PCIe differential transmit pair

5.1.2.6 USB 2.0

Table 5-12 USB 2.0 pins

Pin name	Type	Description
USB2_CFG	I	Double data rate enable

Pin name	Type	Description
USB2_CLK	I	PHY input clock (60 MHz)
USB2_DAT[7:0]	IO	USB data
USB2_DIR	I	USB data direction control Controls the direction of the bidirectional data bus
USB2_NXT	I	ULPI next data Indicates when the PHY has accepted the current byte from the link
USB2_STP	O	ULPI stop data The link asserts this signal for one clock cycle to stop the current data stream to the data bus

5.1.2.7 1 Gb Ethernet

Table 5-13 GMAC pins

Pin name	Type	Description
G0_GP_IN	I	General purpose input
G0_GP_OUT	O	General purpose output
G0_MDC	O	Management data clock (up to 2.5 MHz)
G0_MDIO	IO	Management data input/output
G0_RX_CLK	I	Receive reference clock (125 MHz in 1 Gbps, 25 MHz in 100 Mbps, 2.5 MHz in 10 Mbps mode)
G0_RX_DAT[3:0]	I	Receive data
G0_RX_DEN	I	Receive data enable
G0_TX_CLK	O	Transmit reference clock (125 MHz in 1 Gbps, 25 MHz in 100 Mbps, 2.5 MHz in 10 Mbps mode)
G0_TX_DAT[3:0]	O	Transmit data
G0_TX_DEN	O	Transmit data enable
G1_GP_IN	I	General purpose input
G1_GP_OUT	O	General purpose output
G1_MDC	O	Management data clock (up to 2.5 MHz)
G1_MDIO	IO	Management data input/output
G1_RX_CLK	I	Receive reference clock (125 MHz in 1 Gbps, 25 MHz in 100 Mbps, 2.5 MHz in 10 Mbps mode)
G1_RX_DAT[0...3]	I	Receive data
G1_RX_DEN	I	Receive data enable
G1_TX_CLK	O	Transmit reference clock (125 MHz in 1 Gbps, 25 MHz in 100 Mbps, 2.5 MHz in 10 Mbps mode)
G1_TX_DAT[3:0]	O	Transmit data
G1_TX_DEN	O	Transmit data enable

5.1.3 Low Speed Peripherals

5.1.3.1 GPIOx32

Table 5-14 GPIOx32 pins

Pin name	Type	Description
GPIO32[31:0]	IO	GPIO data

5.1.3.2 UART

Table 5-15 UART pins

Pin name	Type	Description
UART1_RXD	I	Receive data
UART1_TXD	O	Transmit data
UART2_RXD	I	Receive data
UART2_TXD	O	Transmit data

5.1.3.3 QSPI

Table 5-16 QSPI pins

Pin name	Type	Description
SPI1_CLK	O	Output clock
SPI1_IO[3:0]	IO	I/O data
SPI1_SS_N[1:0]	O	Slave select

5.1.3.4 I²C/SMBus

Table 5-17 I²C/SMBus pins

Pin name	Type	Description
SMB2_ALERT	IO	I ² C/SMBus alert
SMB2_CLK	IO	I ² C/SMBus clock
SMB2_DATA	IO	I ² C/SMBus data
SMB2_SUSIN	I	I ² C/SMBus suspend in
SMB2_SUSOUT	O	I ² C/SMBus suspend out
SMB3_ALERT	IO	I ² C/SMBus alert
SMB3_CLK	IO	I ² C/SMBus clock
SMB3_DATA	IO	I ² C/SMBus data
SMB3_SUSIN	I	I ² C/SMBus suspend in
SMB3_SUSOUT	O	I ² C/SMBus suspend out
SMB4_ALERT	IO	I ² C/SMBus alert
SMB4_CLK	IO	I ² C/SMBus clock
SMB4_DATA	IO	I ² C/SMBus data
SMB4_SUSIN	I	I ² C/SMBus suspend in

Pin name	Type	Description
SMB4_SUSOUT	O	I ² C/SMBus suspend out

5.1.3.5 GPIOx16/eSPI

Table 5-18 GPIOx16/eSPI pins

Pin name	Type	Description
GPIO16_D0_ESPI_IO0	IO	GPIO data or eSPI data
GPIO16_D1_ESPI_IO1	IO	GPIO data or eSPI data
GPIO16_D10_ESPI_ALERT1_N	IO	GPIO data or eSPI alert
GPIO16_D11_ESPI_ALERT2_N	IO	GPIO data or eSPI alert
GPIO16_D12_ESPI_ALERT3_N	IO	GPIO data or eSPI alert
GPIO16_D13_ESPI_RESET_N	IO	GPIO data or eSPI reset
GPIO16_D14	IO	GPIO data or drive 0
GPIO16_D15	IO	GPIO data or drive 0
GPIO16_D2_ESPI_IO2	IO	GPIO data or eSPI data
GPIO16_D3_ESPI_IO3	IO	GPIO data or eSPI data
GPIO16_D4_ESPI_SS0_N	IO	GPIO data or eSPI slave select
GPIO16_D5_ESPI_SS1_N	IO	GPIO data or eSPI slave select
GPIO16_D6_ESPI_SS2_N	IO	GPIO data or eSPI slave select
GPIO16_D7_ESPI_SS3_N	IO	GPIO data or eSPI slave select
GPIO16_D8_ESPI_CLK	IO	GPIO data or eSPI clock
GPIO16_D9_ESPI_ALERT0_N	IO	GPIO data or eSPI alert

5.1.3.6 GPIOx8/QSPI

Table 5-19 GPIOx8/QSPI pins

Pin name	Type	Description
GPIO8_C0_SPI2_IO0	IO	GPIO data or QSPI data
GPIO8_C1_SPI2_IO1	IO	GPIO data or QSPI data
GPIO8_C2_SPI2_IO2	IO	GPIO data or QSPI data
GPIO8_C3_SPI2_IO3	IO	GPIO data or QSPI data
GPIO8_C4_SPI2_CLK	IO	GPIO data or QSPI clock
GPIO8_C5_SPI2_SS0_N	IO	GPIO data or QSPI slave select
GPIO8_C6_SPI2_SS1_N	IO	GPIO data or QSPI slave select
GPIO8_C7	IO	GPIO data or drive 0

5.1.3.7 GPIOx8 or I²C/SMBus + I²C/SMBus + UART

Table 5-20 GPIOx8 or I²C/SMBus + I²C/SMBus + UART pins

Pin name	Type	Description
GPIO8_B0_UART3_RXD	IO	GPIO data or UART data in
GPIO8_B1_UART3_TXD	IO	GPIO data or UART data out
GPIO8_B2_SMB5_CLK	IO	GPIO data or I ² C/SMBus clock
GPIO8_B3_SMB5_DATA	IO	GPIO data or I ² C/SMBus data
GPIO8_B4_SMB6_CLK	IO	GPIO data or I ² C/SMBus clock
GPIO8_B5_SMB6_DATA	IO	GPIO data or I ² C/SMBus data
GPIO8_B6	IO	GPIO data or drive 0
GPIO8_B7	IO	GPIO data or drive 0

5.1.4 System Control

Table 5-21 System control pins

Pin name	Type	Description
BOOT_MODE	I	Boot mode select
CMN_TEST_CLK	O	CMN divided by 64 clock
GPIO8_A0	IO	SCP GPIO data
GPIO8_A1	IO	SCP GPIO data
GPIO8_A2	IO	SCP GPIO data
GPIO8_A3	IO	SCP GPIO data
GPIO8_A4	IO	SCP GPIO data
GPIO8_A5	IO	SCP GPIO data
GPIO8_A6	IO	SCP GPIO data
GPIO8_A7	IO	SCP GPIO data
REFCLK	I	PLL reference clock (25 or 100 MHz) For details, refer to Reference Clock
REFCLK_SEL	I	Reference clock selection: <ul style="list-style-type: none"> • 0: 25 MHz • 1: 100 MHz NOTE: The signal level must correspond to PLL reference clock value.
RESET_N	I	Power on reset
SMB0_ALERT	IO	SCP SMBus alert
SMB0_CLK	IO	SCP SMBus clock
SMB0_DATA	IO	SCP SMBus data
SMB0_SUSIN	I	SCP SMBus suspend in
SMB0_SUSOUT	O	SCP SMBus suspend out

Pin name	Type	Description
SMB1_ALERT	IO	SCP SMBus alert
SMB1_CLK	IO	SCP SMBus clock
SMB1_DATA	IO	SCP SMBus data
SMB1_SUSIN	I	SCP SMBus suspend in
SMB1_SUSOUT	O	SCP SMBus suspend out
SPI0_CLK	O	SCP SPI clock
SPI0_RXD	I	SCP SPI data in
SPI0_SS_N[1:0]	O	SCP SPI slave select
SPI0_TRAIN_OFF	I	SPI training off
SPI0_TXD	O	SCP SPI data out
UART0_RXD	I	SCP UART receive data
UART0_TXD	O	SCP UART transmit data
WDT_RESET	O	WDT reset

5.1.5 System Debug

Table 5-22 System debug pins

Pin name	Type	Description
CS_TCK	I	CoreSight input clock
CS_TDI	I	CoreSight data in
CS_TDO	O	CoreSight data out
CS_TMS	I	CoreSight test mode
CS_TRST_N	I	CoreSight reset

5.1.6 Power and Ground

5.1.6.1 Core Supply

Table 5-23 Core supply pins

Pin name	Type	Description
VDD	P	Core power (0.9 V default)

5.1.6.2 0.85V Voltage Supply

Table 5-24 0.85V voltage supply pins

Pin name	Type	Description
VDD_PCIE0_VP	P	PCIe analog voltage supply (0.85 V)
VDD_PCIE1_VP	P	PCIe analog voltage supply (0.85 V)
VDD_PCIE2_VP	P	PCIe analog voltage supply (0.85 V)
VDD_PCIE3_VP	P	PCIe analog voltage supply (0.85 V)

Pin name	Type	Description
VDD_PCIE4_VP	P	PCIe analog voltage supply (0.85 V)

5.1.6.3 PLL Supply

Table 5-25 PLL supply pins

Pin name	Type	Description
VDD_PLL	P	PLL analog voltage supply (1.8 V)

5.1.6.4 DDR Supply

Table 5-26 DDR supply pins

Pin name	Type	Description
VDDQ012	P	DDR VDDQ voltage supply (1.2 V for DDR4)
VDDQ345	P	DDR VDDQ voltage supply (1.2 V for DDR4)

5.1.6.5 DDR PLL Supply

Table 5-27 DDR PLL supply pins

Pin name	Type	Description
VDD_DDR_PLL	P	DDR PLL voltage supply (1.8 V default)

5.1.6.6 1.8V Voltage Supply

Table 5-28 1.8V voltage supply pins

Pin name	Type	Description
VDD_PCIE0_VPH	P	PCIe I/O Voltage supply (1.8 V default)
VDD_PCIE1_VPH	P	PCIe I/O Voltage supply (1.8 V default)
VDD_PCIE2_VPH	P	PCIe I/O Voltage supply (1.8 V default)
VDD_PCIE3_VPH	P	PCIe I/O Voltage supply (1.8 V default)
VDD_PCIE4_VPH	P	PCIe I/O Voltage supply (1.8 V default)
VDD_PVT	P	PVT analog voltage supply (1.8 V)
VDDIO	P	IO voltage supply (1.8 V)

5.1.6.7 Ground

Table 5-29 Ground pins

Pin name	Type	Description
VSS	G	Core ground supply
VSSIO	G	IO ground supply

5.1.7 Requirements for Unused Pins

The following table shows the requirements for unused pins of the BE-S1000. Please follow these requirements if you are not going to use any interface from [Pinout List](#).

Table 5-30 Requirements for unused pins

Type	Requirements
Input pins	Tie to ground potential If active level is low, tie to power supply
Output pins	Leave floating
Power pins	Always use
Reserved pins	Leave floating

Preliminary Datasheet

5.2 Pin Map Overview

The following diagram shows ball map from the top view of the package.

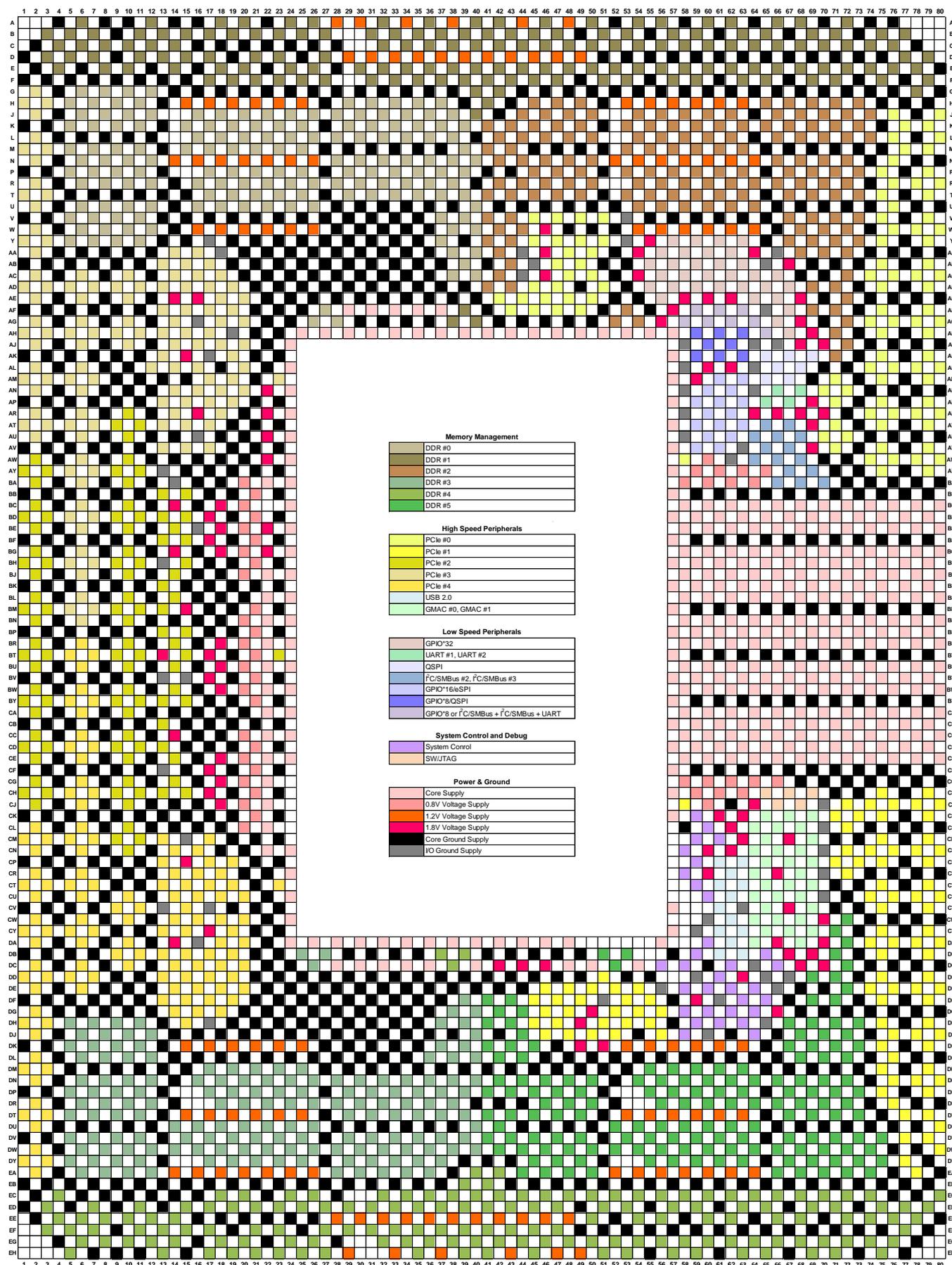


Figure 5-1 BE-S1000 pin map

5.2.1 Power and Ground

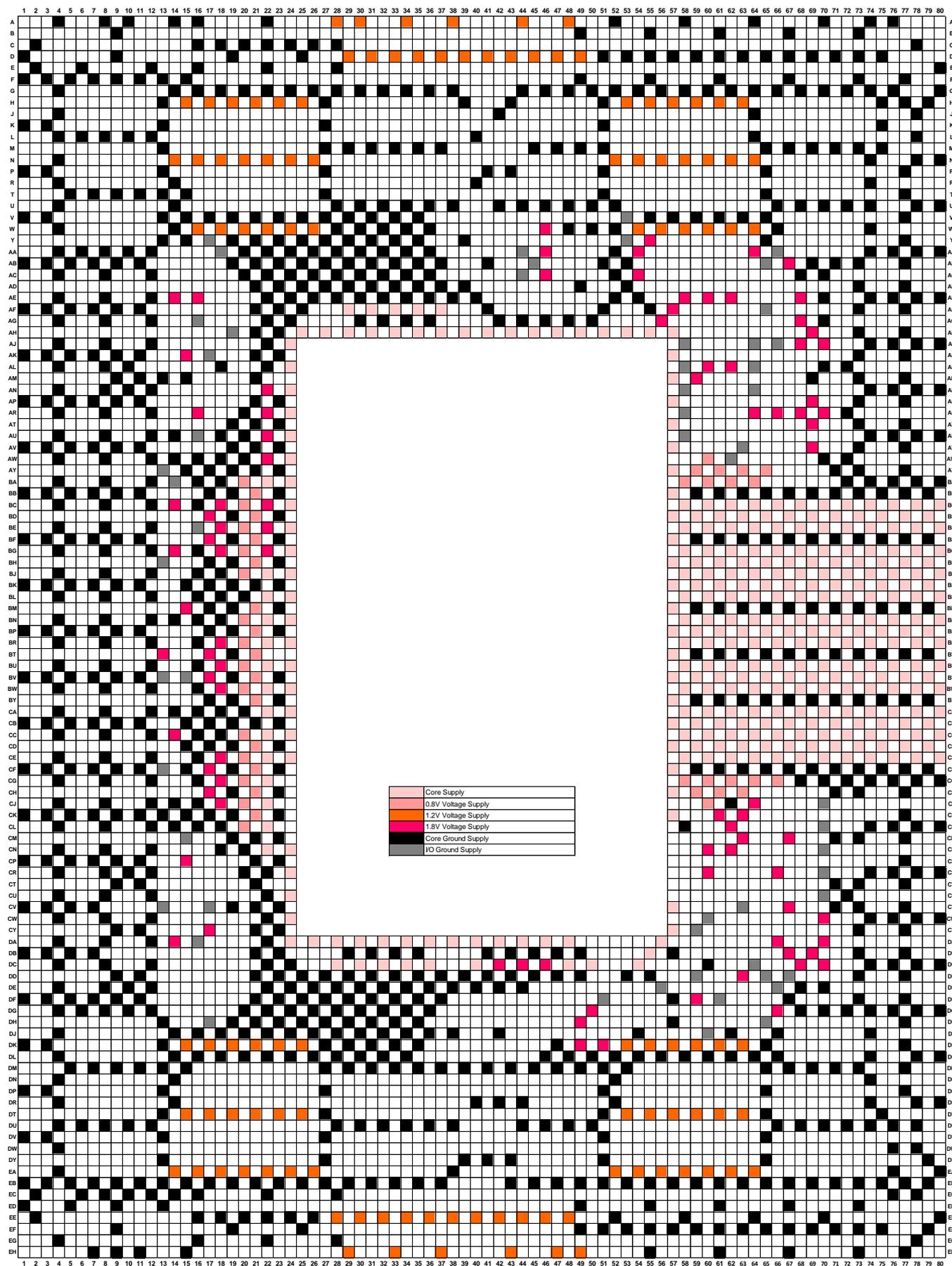


Figure 5-2 Power and ground pin placement

5.2.2 High Speed Peripherals

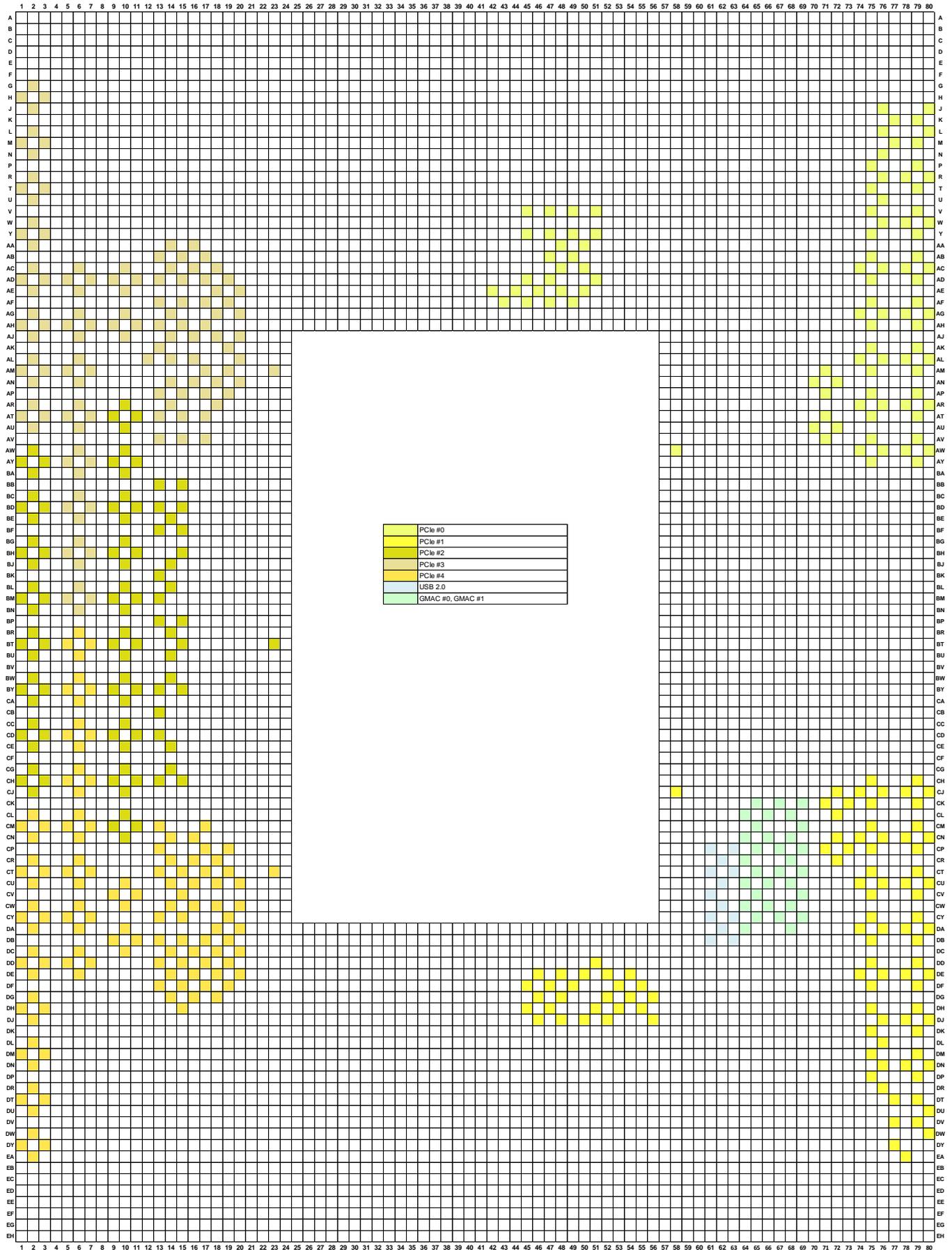


Figure 5-3 High speed peripherals pin placement

5.2.3 Low Speed Peripherals

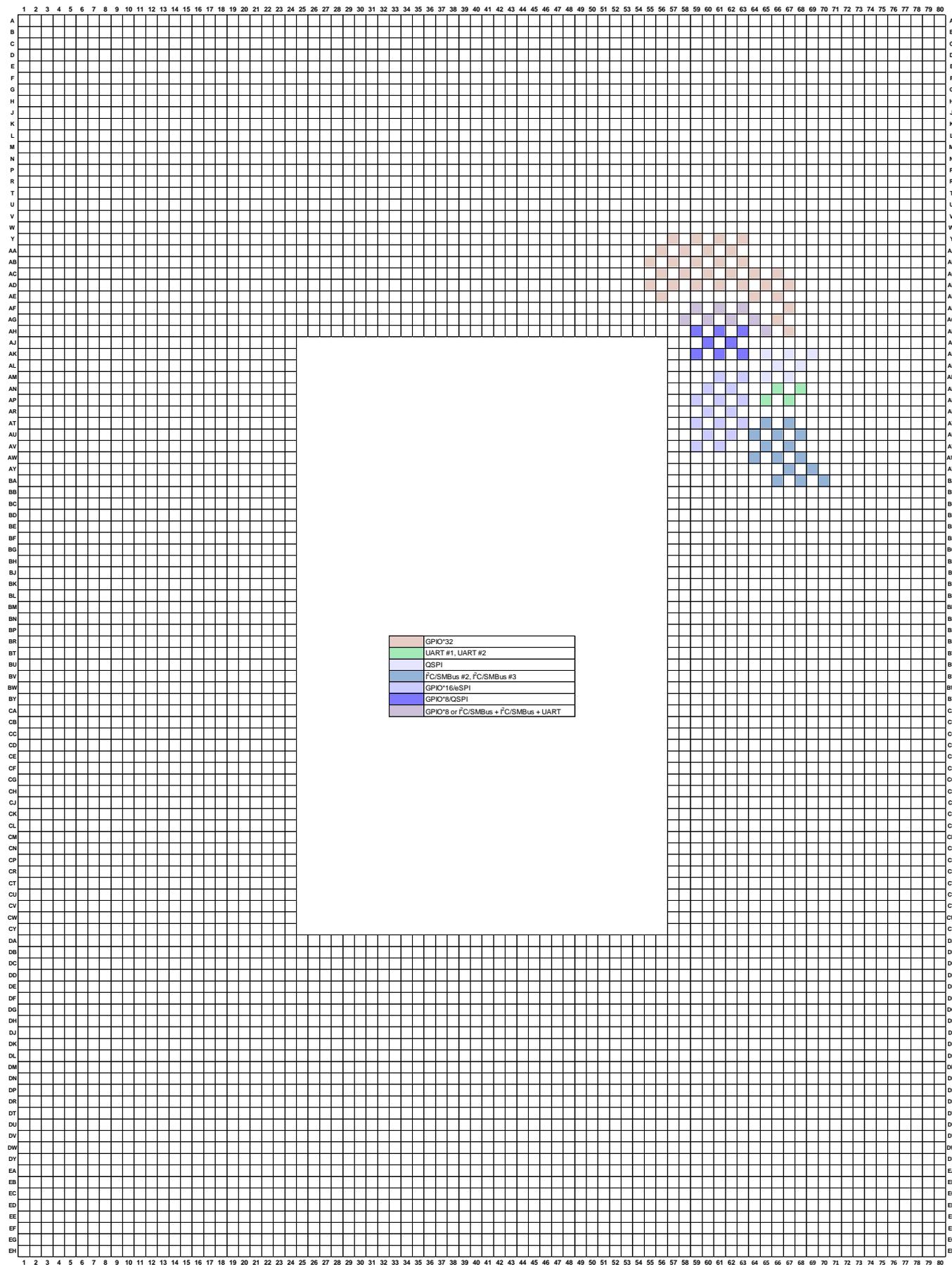


Figure 5-4 Low speed peripherals pin placement

5.2.4 Memory

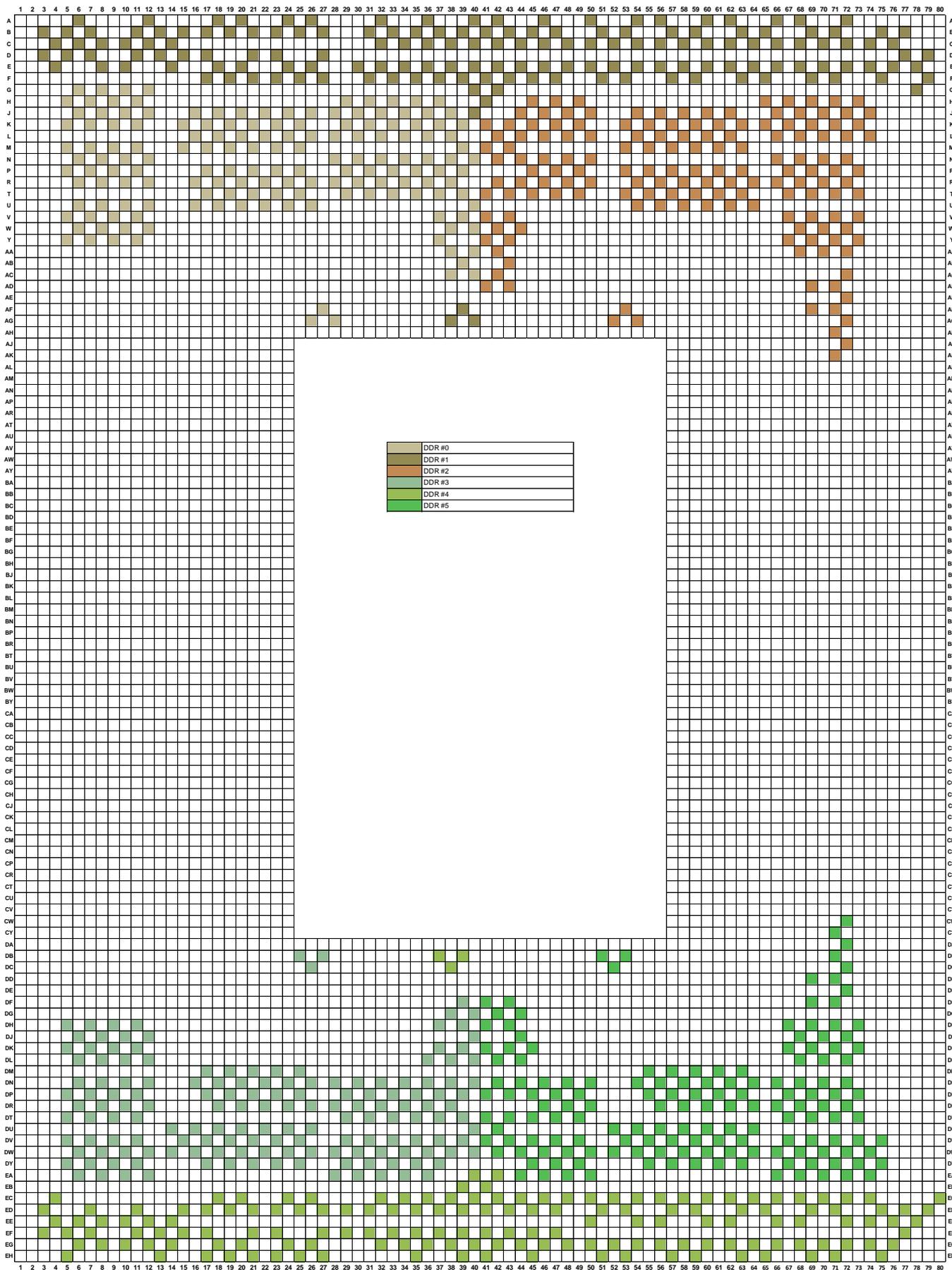


Figure 5-5 Memory pin placement

5.2.5 System Control and Debug

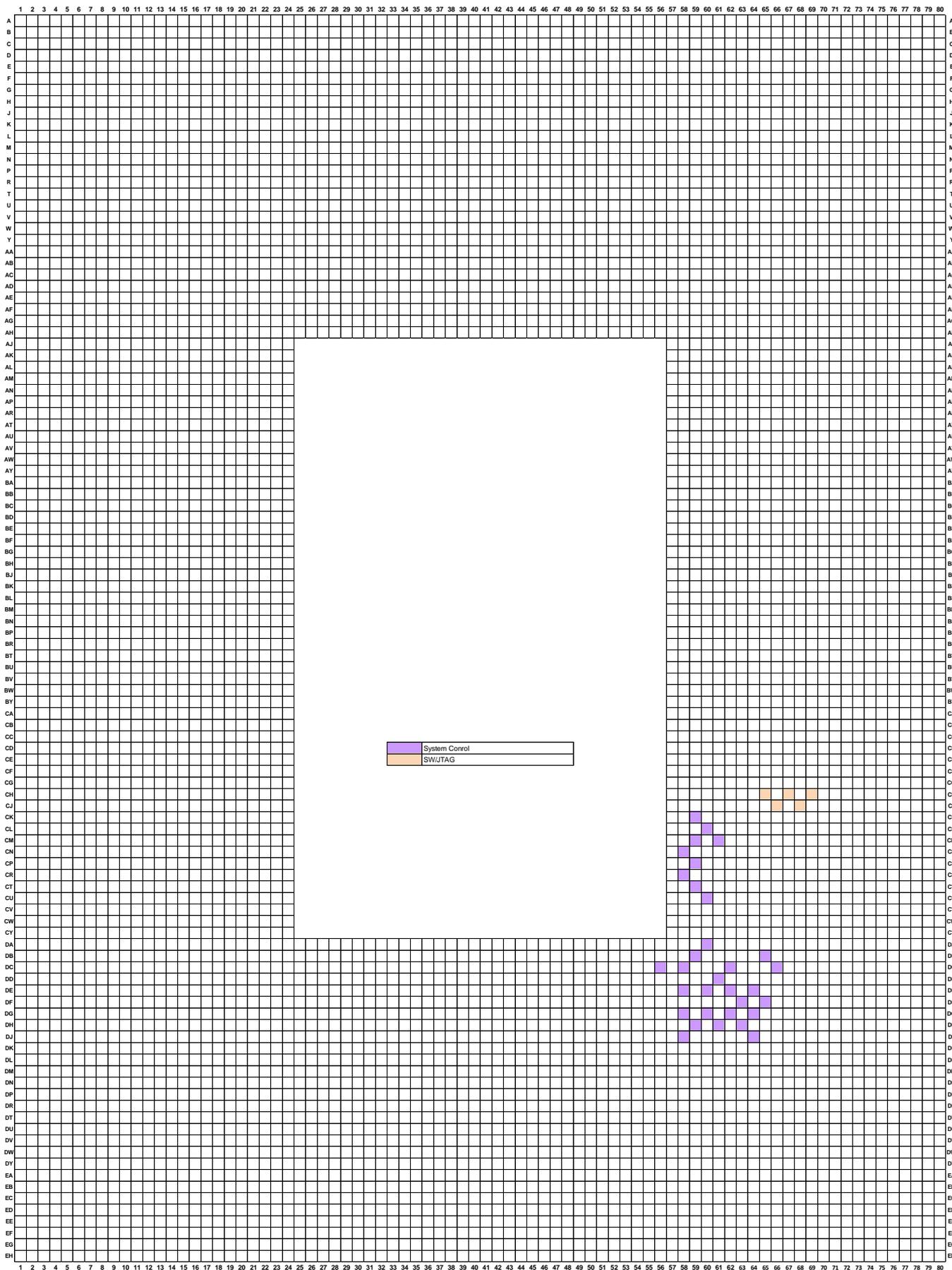


Figure 5-6 System control and debug pin placement

5.2.6 Detailed Pin Map

The following figure shows the division of [BE-S1000 pin map](#) into twelve sections (A, B, C, D, E, F, G, H, I and J).

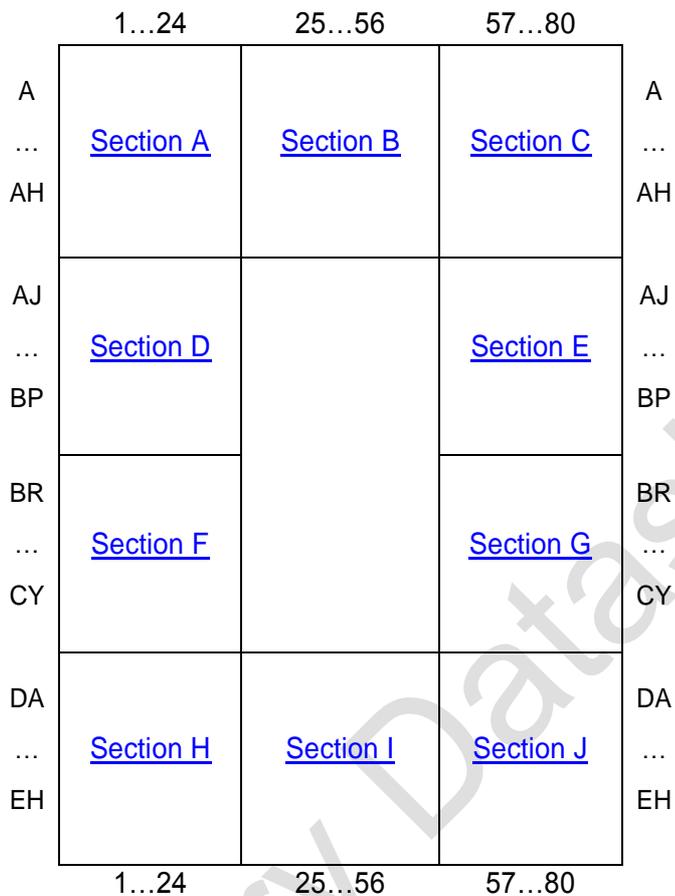


Figure 5-7 BE-S1000 pin map division

5.2.6.1 Section A

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24						
A				VSS		DDR1_DQS_DP[7]		VSS		VSS		DDR1_DQS_DP[6]		VSS		VSS		DDR1_DQ[46]		DDR1_DQS_DP[14]		VSS		DDR1_DQ[38]	A					
B			DDR1_DQ[57]		DDR1_DQS_DP[7]		DDR1_DQ[57]		VSS		DDR1_DQ[55]		DDR1_DQS_DP[6]		DDR1_DQ[53]		DDR1_DQ[45]		DDR1_DQS_DP[14]		DDR1_DQ[45]		DDR1_DQ[38]		DDR1_DQ[38]	B				
C		VSS		DDR1_DQ[62]		DDR1_DQS_DP[14]		DDR1_DQ[61]		DDR1_DQ[61]		DDR1_DQS_DP[15]		DDR1_DQ[49]		VSS		VSS		VSS		VSS		VSS		VSS	C			
D	VSS		DDR1_DQ[55]		DDR1_DQS_DP[15]		DDR1_DQ[55]		VSS		DDR1_DQ[51]		DDR1_DQS_DP[13]		DDR1_DQ[53]		DDR1_DQ[45]		VSS		DDR1_DQ[45]		DDR1_DQ[38]		DDR1_DQ[38]	D				
E		VSS		DDR1_DQ[63]		VSS		DDR1_DQ[60]		DDR1_DQ[60]		VSS		DDR1_DQ[48]		VSS		DDR1_DQS_DP[5]		DDR1_DQ[41]		VSS		DDR1_DQ[38]		DDR1_DQS_DP[14]	E			
F	VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		DDR1_DQ[47]		DDR1_DQS_DP[3]		DDR1_DQ[49]		DDR1_DQ[38]		DDR1_DQ[38]	F				
G		PCIE3_TX_DP[8]		VSS		DDR0_DQ[65]		DDR0_DQ[38]		DDR0_DQS_DP[4]		DDR0_DQ[37]		VSS		VSS		VSS		VSS		VSS		VSS		VSS	G			
H	PCIE3_TX_DP[1]		PCIE3_TX_DN[2]		DDR0_DQ[61]		DDR0_DQ[34]		DDR0_DQS_DP[4]		DDR0_DQ[33]		VSS		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012	H		
J		PCIE3_TX_DN[1]		VSS		DDR0_DQ[56]		DDR0_DQ[39]		DDR0_DQS_DP[15]		DDR0_DQ[36]		DDR0_A[17]		DDR0_CS_N[5]		DDR0_CLK_DN[3]		DDR0_A[11]		DDR0_A[11]		DDR0_A[8]		DDR0_A[8]	J			
K	VSS		VSS		DDR0_DQ[57]		DDR0_DQ[35]		DDR0_DQS_DP[15]		DDR0_DQ[32]		VSS		DDR0_ODT[5]		DDR0_ODT[2]		DDR0_A[10]		DDR0_CLK_DP[3]		DDR0_A[8]		DDR0_A[8]		DDR0_A[8]	K		
L		PCIE3_TX_DP[2]		VSS		VSS		VSS		VSS		VSS				DDR0_CS_N[3]		DDR0_A[14]		DDR0_CLK_DN[1]		DDR0_A[2]		DDR0_A[11]		DDR0_A[11]	L			
M	PCIE3_TX_DP[3]		PCIE3_TX_DN[2]		DDR0_DQS_DP[16]		DDR0_DQ[43]		DDR0_DQS_DP[5]		DDR0_DQ[41]		VSS		DDR0_ODT[1]		DDR0_ODT[8]		DDR0_BA[1]		DDR0_CLK_DP[1]		DDR0_A[9]		DDR0_A[9]		DDR0_A[9]	M		
N		PCIE3_TX_DN[3]		VSS		DDR0_DQS_DP[15]		DDR0_DQ[47]		DDR0_DQS_DP[5]		DDR0_DQ[45]		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012	N	
P	VSS		VSS		DDR0_DQS_DP[7]		DDR0_DQ[42]		DDR0_DQS_DP[14]		DDR0_DQ[40]		VSS				DDR0_A[15]		DDR0_A[8]		DDR0_CLK_DP[2]		DDR0_A[8]		DDR0_A[8]		DDR0_A[8]	P		
R		PCIE3_TX_DP[4]		VSS		DDR0_DQS_DP[7]		DDR0_DQ[46]		DDR0_DQS_DP[15]		DDR0_DQ[44]		VSS		DDR0_CS_N[2]		DDR0_A[16]		DDR0_CLK_DN[2]		DDR0_A[3]		DDR0_A[12]		DDR0_A[12]	R			
T	PCIE3_TX_DP[5]		PCIE3_TX_DN[2]		VSS		VSS		VSS		VSS		VSS		VSS		DDR0_CS_N[2]		DDR0_PAR		DDR0_CLK_DP[2]		DDR0_A[7]		DDR0_A[7]		DDR0_A[7]	T		
U		PCIE3_TX_DN[5]		VSS		DDR0_DQ[62]		DDR0_DQ[59]		DDR0_DQS_DP[6]		DDR0_DQ[58]		VSS		DDR0_A[13]		DDR0_BA[0]		DDR0_CLK_DN[5]		DDR0_A[4]		DDR0_A[4]		DDR0_A[4]	U			
V	VSS		VSS		DDR0_DQ[63]		DDR0_DQ[55]		DDR0_DQS_DP[6]		DDR0_DQ[49]		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS	V		
W		PCIE3_TX_DP[6]		VSS		DDR0_DQ[58]		DDR0_DQ[54]		DDR0_DQS_DP[15]		DDR0_DQ[52]		VSS		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012		VDDQ012	W	
Y	PCIE3_TX_DP[7]		PCIE3_TX_DN[4]		DDR0_DQ[66]		DDR0_DQ[50]		DDR0_DQS_DP[15]		DDR0_DQ[48]		VSS		VSS		VSSIO		VSS		VSS		VSS		VSS		VSS	Y		
AA		PCIE3_TX_DN[7]		VSS		VSS		VSS		VSS		VSS		PCIE3_ATT_IND[0]		PCIE3_ATT_BUT[1]		VSSIO		VSS		VSS		VSS		VSS		VSS	AA	
AB	VSS		VSS		VSS		VSS		VSS		VSS		PCIE3_ATT_IND[0]		PCIE3_ATT_IND[1]		PCIE3_ATT_BUT[0]		VSS		VSS		VSS		VSS		VSS		VSS	AB
AC		PCIE3_TX_DP[8]		VSS		PCIE3_RX_DP[2]		VSS		PCIE3_CLK_3_DP		VSS		PCIE3_ATT_IND[0]		PCIE3_ATT_IND[3]		PCIE3_ATT_BUT[2]		VSS		VSS		VSS		VSS		VSS	AC	
AD	PCIE3_TX_DP[9]		PCIE3_TX_DN[5]		PCIE3_RX_DP[1]		PCIE3_RX_DN[3]		PCIE3_CLK_2_DP		PCIE3_CLK_3_DN		PCIE3_ATT_IND[0]		PCIE3_ATT_IND[4]		PCIE3_ATT_BUT[3]		PCIE3_CM_D_INT[1]		VSS		VSS		VSS		VSS		VSS	AD
AE		PCIE3_TX_DN[9]		VSS		PCIE3_RX_DN[1]		VSS		PCIE3_CLK_2_DN		VSS		VDDIO		VDDIO		PCIE3_CM_D_INT[2]		PCIE3_INT_RL_CTRL[0]		VSS		VSS		VSS		VSS	AE	
AF	VSS		VSS		VSS		VSS		VSS		VSS		PCIE3_PE_RST_M[1]		PCIE3_ATT_IND[7]		PCIE3_CM_D_INT[0]		PCIE3_INT_RL_CTRL[1]		VSS		VSS		VSS		VSS		VSS	AF
AG		PCIE3_TX_DP[10]		VSS		PCIE3_RX_DP[2]		VSS		PCIE3_CLK_1_DP		VSS		PCIE3_INT_RL_ENG[0]		VSSIO		PCIE3_MR_L_SEN[0]		PCIE3_CM_D_INT[3]		VSS		VSS		VSS		VSS	AG	
AH	PCIE3_TX_DP[11]		PCIE3_TX_DN[10]		PCIE3_RX_DP[3]		PCIE3_RX_DN[2]		PCIE3_CLK_0_DP		PCIE3_CLK_1_DN		PCIE3_PR_RST_M[2]		PCIE3_INT_RL_ENG[1]		PCIE3_INT_RL_ENG[2]		VSSIO		VSS		VSS		VSS		VSS		VSS	AH

Figure 5-8 BE-S1000 pin map (section A)

5.2.6.3 Section C

	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80		
A		VSS		DDR1_DQ[24]	DDR1_DQ[18]		VSS		DDR1_DQ[16]	DDR1_DQ[11]		VSS		DDR1_DQ[8]		VSS		VSS							A	
B	DDR1_DQS[30]		DDR1_DQS[DP13]	VSS		DDR1_DQ[22]	DDR1_DQS[DP11]		VSS		DDR1_DQ[14]	DDR1_DQS[DP10]		VSS		DDR1_DQ[7]		DDR1_DQS[DN8]							B	
C		DDR1_DQS[DN12]	DDR1_DQ[26]	DDR1_DQ[18]	DDR1_DQS[DN11]	DDR1_DQ[21]	DDR1_DQ[10]	DDR1_DQ[10]	DDR1_DQS[DN10]	DDR1_DQ[13]	DDR1_DQ[3]	DDR1_DQS[DP9]		VSS								VSS			C	
D	VSS		VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	DDR1_DQS[DP8]	DDR1_DQ[5]				D	
E		DDR1_DQS[DN9]	DDR1_DQ[28]	DDR1_DQ[23]	DDR1_DQS[DN2]	DDR1_DQ[20]	DDR1_DQ[15]	DDR1_DQ[15]	DDR1_DQS[DN1]	DDR1_DQ[12]	DDR1_DQ[2]	DDR1_DQS[DN9]										DDR1_DQ[1]		VSS	E	
F	DDR1_DQS[DP5]	DDR1_DQ[25]	VSS		DDR1_DQS[DP2]	DDR1_DQ[17]		VSS		DDR1_DQS[DP1]	DDR1_DQ[9]	VSS		DDR1_DQ[6]	VSS	DDR1_DQ[6]	VSS		VSS		DDR1_DQ[4]				F	
G		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		DDR1_DQ[6]		VSS		G
H	VDD0012		VDD0012		VDD0012		VDD0012		DDR2_ECC[3]	DDR2_DQS[DP18]	DDR2_ECC[1]	DDR2_DQ[11]	DDR2_DQS[DP11]		VSS		VSS		VSS						H	
J		DDR2_CLK[DP8]	DDR2_A[3]	DDR2_A[12]		VSS		DDR2_ECC[7]	DDR2_DQS[DN9]	DDR2_ECC[9]	DDR2_DQ[15]	DDR2_DQS[DN1]	DDR2_CLK[DP9]		VSS		PCIE0_RX[DP9]		VSS				PCIE0_TX[DP9]		J	
K	DDR2_CLK[DN3]	DDR2_A[1]	DDR2_A[8]	DDR2_CKE[2]	DDR2_ECC[2]	DDR2_DQS[DN17]	DDR2_ECC[9]	DDR2_DQ[10]	DDR2_DQS[DN10]		VSS		PCIE0_RX[DN0]		VSS		PCIE0_RX[DN0]		VSS		PCIE0_TX[DP11]				K	
L		DDR2_CLK[DP11]	DDR2_A[4]	DDR2_ALE[ET,N]	VSS		DDR2_ECC[8]	DDR2_DQS[DP13]	DDR2_ECC[4]	DDR2_DQ[14]	DDR2_DQS[DP10]		VSS		PCIE0_RX[DP11]		VSS		VSS		PCIE0_TX[DN6]				L	
M	DDR2_CLK[DN1]	DDR2_A[2]	DDR2_A[7]	DDR2_CKE[3]		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		PCIE0_RX[DN11]		PCIE0_TX[DN11]		M
N		VDD0013		VDD0013		VDD0013		VDD0013		DDR2_DQ[27]	DDR2_DQS[DP13]	DDR2_DQ[25]	DDR2_DQ[8]	DDR2_DQ[8]	VSS		PCIE0_RX[DP10]		VSS				VSS		N	
P	DDR2_A[9]	DDR2_CLK[DP2]	DDR2_A[9]	DDR2_ACT[DN]		VSS		DDR2_DQ[31]	DDR2_DQS[DN3]	DDR2_DQ[26]	DDR2_DQ[8]	DDR2_DQ[8]	DDR2_DQ[8]	PCIE0_RX[DN2]		VSS		VSS		PCIE0_TX[DP2]					P	
R	DDR2_CLK[DN2]	DDR2_A[8]	DDR2_A[5]	DDR2_CKE[1]	DDR2_DQ[20]	DDR2_DQS[DN12]	DDR2_DQ[24]	DDR2_DQS[DN13]	DDR2_DQ[24]	DDR2_DQ[13]		VSS		PCIE0_RX[DP3]		PCIE0_TX[DP3]		PCIE0_TX[DN2]							R	
T	DDR2_PRR	DDR2_CLK[DP1]	DDR2_A[11]	DDR2_CKE[3]		VSS		DDR2_DQ[30]	DDR2_DQS[DP12]	DDR2_DQ[28]	DDR2_DQ[12]	DDR2_DQ[12]	PCIE0_RX[DN3]		VSS		PCIE0_TX[DN3]								T	
U	DDR2_CLK[DN0]	DDR2_A[5]	DDR2_B[9]	DDR2_RESET,N	VSS		VSS		VSS		VSS		VSS		VSS		PCIE0_RX[DP4]		VSS		VSS		VSS		U	
V	VSS		VSS		VSS		VSS		DDR2_DQ[19]	DDR2_DQS[DP2]	DDR2_DQ[17]	DDR2_DQ[2]	DDR2_DQ[2]	PCIE0_RX[DN4]		VSS		PCIE0_TX[DP4]							V	
W		VDD0014		VDD0014		VDD0014		VDD0014		VSS		DDR2_DQ[23]	DDR2_DQS[DN2]	DDR2_DQ[3]	VSS		PCIE0_RX[DP5]		PCIE0_TX[DP5]		PCIE0_TX[DN4]				W	
Y	GPIO3[15]	GPIO3[10]	GPIO3[15]	GPIO3[20]		VSS		DDR2_DQ[16]	DDR2_DQS[DN11]	DDR2_DQ[16]	DDR2_DQ[6]	DDR2_DQ[6]	PCIE0_RX[DN5]		VSS		VSS		VSS		PCIE0_TX[DN5]				Y	
AA		GPIO3[8]	GPIO3[13]	GPIO3[18]	VDDIO		VSSIO	DDR2_DQ[22]	DDR2_DQS[DP11]	DDR2_DQ[7]		VSS		VSS		VSS		VSS		VSS		VSS		VSS	AA	
AB	GPIO3[6]	GPIO3[11]	GPIO3[16]	GPIO3[21]	VSSIO		VDDIO		VSS		VSS		VSS		VSS		PCIE0_RX[DP6]		VSS		PCIE0_TX[DP6]				AB	
AC		GPIO3[9]	GPIO3[14]	GPIO3[19]	GPIO3[23]	GPIO3[26]		VSS		VSS		DDR2_DQS[DN9]		VSS		PCIE0_RX[DP7]		PCIE0_RX[DN6]		PCIE0_TX[DP7]		PCIE0_TX[DN6]			AC	
AD	GPIO3[7]	GPIO3[12]	GPIO3[17]	GPIO3[22]	GPIO3[25]	GPIO3[29]	DDR2_DQ[21]	DDR2_DQS[DP9]		VSS		PCIE0_RX[DN7]		VSS		PCIE0_TX[DN7]		VSS		VSS		PCIE0_TX[DN7]			AD	
AE		VDDIO		VDDIO		VDDIO		GPIO3[24]	GPIO3[27]	VDDIO		VSS		DDR2_DQS[DP5]		VSS		VSS		VSS		VSS		VSS		AE
AF	VDDIO	GPIO0_B1, UART3_TX,D	GPIO0_B2, SMBUS_CLK	GPIO0_B4, SMBUS_DAT,A	GPIO0_B6	GPIO3[30]	DDR2_DQ[20]	DDR2_DQS[DN0]		VSS		PCIE0_RX[DP8]		VSS		PCIE0_TX[DP8]		VSS		VSS		PCIE0_TX[DP8]			AF	
AG	GPIO0_B5, UART3_RX,D	GPIO0_B3, SMBUS_DAT,A	GPIO0_B7, SMBUS_CLK	GPIO0_B8	GPIO3[28]	VDDIO		VSS		DDR2_DQ[1]		PCIE0_RX[DP9]		PCIE0_RX[DN8]		PCIE0_TX[DP9]		PCIE0_TX[DN8]						PCIE0_TX[DN8]	AG	
AH	VDD	GPIO0_C0, SP2_I00	GPIO0_C2, SP2_I02	GPIO0_C4, SP2_CLK	GPIO0_B7	GPIO3[31]	VDDIO		DDR2_DQ[1]		VSS		PCIE0_RX[DN9]		VSS		VSS		VSS					PCIE0_TX[DN9]	AH	

Figure 5-10 BE-S1000 pin map (section C)

5.2.6.4 Section D

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24		
AJ		PCIE3_TX_DN[11]		VSS		PCIE3_RX_DN[4]		VSS		PCIE3_CLK_0_DN		VSS		PCIE3_INT_RL_EN[2]		PCIE3_PRES_ST[3]		PCIE3_PRES_ST[11]		PCIE3_MRL_SENS[3]		VSS		VDD	AJ	
AK	VSS		VSS		VSS		VSS		VSS		VSS		PCIE3_PWR_FAULT[1]		VDDIO		VSSIO		PCIE3_MRL_SENS[3]		VSS		VSS		AK	
AL		PCIE3_TX_DP[12]		VSS		PCIE3_RX_DP[4]		VSS		VSS		PCIE3_PEST_N[3]		PCIE3_PEST_N[3]		PCIE3_PWR_R_CTRL[3]		VSS		PCIE3_INT_RL_CTRL[3]		VSS		VDD	AL	
AM	PCIE3_TX_DP[13]		PCIE3_TX_DN[12]		PCIE3_RX_DP[5]		PCIE3_RX_DN[4]		VSS		VSS		VSS		VSS		PCIE3_PEST_N[4]		PCIE3_MRL_SENS[2]		VSS		PCIE3_PEST_N[4]		AM	
AN		PCIE3_TX_DN[13]		VSS		PCIE3_RX_DN[5]		VSS		VSS		VSS		PCIE3_PWR_R_CTRL[2]		PCIE3_PWR_R_IND[3]		PCIE3_PWR_R_FAULT[2]		PCIE3_INT_RL_CTRL[2]		VDD_PLL		VDD	AN	
AP	VSS		VSS		VSS		VSS		VSS		VSS		PCIE3_PWR_R_IND[2]		PCIE3_PWR_R_IND[5]		PCIE3_PRES_ST[3]		PCIE3_PWR_R_CTRL[5]		VSS		VSS		AP	
AR		PCIE3_TX_DP[14]		VSS		PCIE3_RX_DP[6]		VSS		PCIE2_RX_DP[5]		VSS		PCIE3_PWR_R_CTRL[1]		VDDIO		PCIE3_PWR_R_FAULT[3]		VSS		VDD_PLL		VDD	AR	
AT	PCIE3_TX_DP[15]		PCIE3_TX_DN[14]		PCIE3_RX_DP[7]		PCIE3_RX_DN[6]		PCIE2_RX_DP[11]		PCIE2_RX_DN[5]		PCIE3_PWR_R_IND[4]		PCIE3_PWR_R_IND[5]		PCIE3_PWR_R_IND[6]		VSS		VSS		VSS		AT	
AU		PCIE3_TX_DN[15]		VSS		PCIE3_RX_DN[7]		VSS		PCIE2_RX_DN[1]		VSS		VSS		VSSIO		VSS		VSS		VSS		VDD_PLL		AU
AV	VSS		VSS		VSS		VSS		VSS		VSS		PCIE3_PWR_R_IND[1]		PCIE3_PWR_R_IND[7]		PCIE3_PWR_R_FAULT[2]		VSS		VSS		VSS		AV	
AW		PCIE2_TX_DP[8]		VSS		PCIE3_RX_DP[8]		VSS		PCIE2_RX_DP[2]		VSS		VSS		VSS		VSS		VSS		VSS		VDD_PLL		AW
AY	PCIE2_TX_DP[1]		PCIE2_TX_DN[9]		PCIE3_RX_DP[9]		PCIE3_RX_DN[8]		PCIE2_RX_DP[3]		PCIE2_RX_DN[2]		VSSIO		VSS		VSS		VSS		VSS		VSS		AY	
BA		PCIE2_TX_DN[1]		VSS		PCIE3_RX_DN[9]		VSS		PCIE2_RX_DN[3]		VSS		VSSIO		VSS		VSS		VDD_PCE_3_VP		VDD		VDD	BA	
BB	VSS		VSS		VSS		VSS		VSS		VSS		PCIE2_PWR_R_IND[3]		PCIE2_PWR_R_CTRL[1]		VSS		VSS		VDD_PCE_3_VP		VSS		BB	
BC		PCIE2_TX_DP[2]		VSS		PCIE3_RX_DP[10]		VSS		PCIE2_RX_DP[4]		VSS		VDDIO		VSS		VDD_PCE_3_VPH		VDD_PCE_3_VP				VDD	BC	
BD	PCIE2_TX_DP[3]		PCIE2_TX_DN[2]		PCIE3_RX_DP[11]		PCIE3_RX_DN[10]		PCIE2_RX_DP[5]		PCIE2_RX_DN[4]		PCIE2_PWR_R_IND[2]		PCIE2_PWR_R_CTRL[3]		VDD_PCE_3_VPH		VSS		VDD_PCE_3_VP		VSS		BD	
BE		PCIE2_TX_DN[3]		VSS		PCIE3_RX_DN[11]		VSS		PCIE2_RX_DN[5]		VSS		PCIE2_PWR_R_IND[1]		VSSIO		VDD_PCE_3_VPH		VDD_PCE_3_VP		VDD_PVT		VDD	BE	
BF	VSS		VSS		VSS		VSS		VSS		VSS		PCIE2_PWR_R_IND[4]		PCIE2_PWR_R_FAULT[2]		VDD_PCE_3_VPH		VSS		VDD_PCE_3_VP		VSS		BF	
BG		PCIE2_TX_DP[4]		VSS		PCIE3_RX_DP[12]		VSS		PCIE2_RX_DP[6]		VSS		VDDIO		VSS		VDD_PCE_3_VPH		VDD_PCE_3_VP		VDD_PVT		VDD	BG	
BH	PCIE2_TX_DP[5]		PCIE2_TX_DN[4]		PCIE3_RX_DP[13]		PCIE3_RX_DN[12]		PCIE2_RX_DP[7]		PCIE2_RX_DN[6]		VSSIO		PCIE2_PWR_R_FAULT[1]		VSS		VSS		VDD_PCE_3_VP		VSS		BH	
BJ		PCIE2_TX_DN[5]		VSS		PCIE3_RX_DN[13]		VSS		PCIE2_RX_DN[7]		VSS		PCIE2_PRES_ST[11]		VSS		VSS		VDD_PCE_3_VP		VDD		VDD	BJ	
BK	VSS		VSS		VSS		VSS		VSS		VSS		PCIE2_ATT_BUT[3]		VSS		VSS		VSS		VSS		VSS		BK	
BL		PCIE2_TX_DP[6]		VSS		PCIE3_RX_DP[14]		VSS		PCIE2_RX_DP[8]		VSS		PCIE2_PRES_ST[10]		VSS		VSS		VSS		VDD		VDD	BL	
BM	PCIE2_TX_DP[7]		PCIE2_TX_DN[6]		PCIE3_RX_DP[15]		PCIE3_RX_DN[14]		PCIE2_RX_DP[9]		PCIE2_RX_DN[8]		PCIE2_ATT_IND[1]		VDDIO		VSS		VSS		VDD_PCE_2_VP		VSS		BM	
BN		PCIE2_TX_DN[7]		VSS		PCIE3_RX_DN[15]		VSS		PCIE2_RX_DN[9]		VSS		VSS		VSS		VSS		VDD_PCE_2_VP		VDD		VDD	BN	
BP	VSS		VSS		VSS		VSS		VSS		VSS		PCIE2_ATT_IND[3]		PCIE2_MRL_SENS[3]		VSS		VSS		VDD_PCE_2_VP		VSS		BP	

Figure 5-11 BE-S1000 pin map (section D)

5.2.6.5 Section E

	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80		
AJ		VSSIO		GPIO16_C1_SPL01		GPIO16_C3_SPL03		VSSIO		VSSIO		VDDIO		VDDIO		DDR2_DQ4		VSS		VSS		VSS		VSS	AJ	
AK	VDD		GPIO16_C2_SPL02_N		GPIO16_C6_SPL06_N		GPIO16_C7		SPI1_CLK		SPI1_Q[1]		SPI1_Q[3]		DDR2_DQ5		VSS		PCIE0_RX_DP[10]		VSS		PCIE0_TX_DP[10]		AK	
AL		VSSIO		VDDIO		VDDIO		VSSIO		SPI1_Q[0]		SPI1_Q[2]		VSS		VSS		PCIE0_RX_DP[11]		PCIE0_RX_DN[10]		PCIE0_TX_DP[11]		PCIE0_TX_DN[10]	AL	
AM	VDD		VDDIO		GPIO16_D1_ESPL01		GPIO16_D3_ESPL03		SPI1_SS_N[0]		SPI1_SS_N[1]		VSS		PCIE0_CLK_3_DP		VSS		PCIE0_RX_DN[11]		VSS		PCIE0_TX_DN[11]		AM	
AN		VSSIO		GPIO16_D0_ESPL00		GPIO16_D2_ESPL02		VSSIO		UART1_RX_D		UART1_TX_D		PCIE0_CLK_2_DP		PCIE0_CLK_3_DN		VSS		VSS		VSS		VSS	AN	
AP	VDD		GPIO16_D6_ESPL06_N		GPIO16_D5_ESPL05_N		GPIO16_D4_ESPL04_N		UART2_RX_D		UART2_TX_D		VDD_PCE0_VPH		PCIE0_CLK_2_DN		VSS		PCIE0_RX_DP[12]		VSS		PCIE0_TX_DP[12]		AP	
AR		VSSIO		GPIO16_D7_ESPL07_N		GPIO16_D8_ESPL08		VDDIO		VDDIO		VDD_PCE0_VPH		VDD_PCE0_VPH		VSS		PCIE0_RX_DP[13]		PCIE0_RX_DN[12]		PCIE0_TX_DP[13]		PCIE0_TX_DN[12]	AR	
AT	VDD		GPIO16_D11_ESPL11_AL_ERT2_N		GPIO16_D10_ESPL10_AL_ERT1_N		GPIO16_D9_ESPL09_ALE_RT2_N		SMB2_CLK		SMB2_SUS_IN		VDD_PCE0_VPH		PCIE0_CLK_1_DP		VSS		PCIE0_RX_DN[13]		VSS		PCIE0_TX_DN[13]		AT	
AU		VSSIO		GPIO16_D12_ESPL12_AL_ERT2_N		GPIO16_D11_ESPL11_AL_ERT1_N		SMB2_DAT_A		SMB2_SUS_OUT		SMB2_ALE_RT		PCIE0_CLK_0_DP		PCIE0_CLK_1_DN		VSS		VSS		VSS		VSS	AU	
AV	VDD		GPIO16_D14		GPIO16_D13_5		VSSIO		SMB3_CLK		SMB3_SUS_IN		VDD_PCE0_VPH		PCIE0_CLK_0_DN		VSS		PCIE0_RX_DP[14]		VSS		PCIE0_TX_DP[14]		AV	
AW		PCIE0_RE_SREF		VDD_PCE0_VPH		VSSIO		SMB3_DAT_A		SMB3_SUS_OUT		SMB3_ALE_RT		VSS		VSS		PCIE0_RX_DP[15]		PCIE0_RX_DN[14]		PCIE0_TX_DP[15]		PCIE0_TX_DN[14]	AW	
AY	VDD		VDD_PCE0_VPH		VDD_PCE0_VPH		VDD_PCE0_VPH		VDD_PCE0_VPH		VDD_PCE0_VPH		SMB4_CLK		SMB4_SUS_IN		VSS		VSS		PCIE0_RX_DN[15]		VSS		PCIE0_TX_DN[15]	AY
BA		VDD_PCE0_VPH		VDD_PCE0_VPH		VDD_PCE0_VPH		VDD_PCE0_VPH		SMB4_DAT_A		SMB4_SUS_OUT		SMB4_ALE_RT		VSS		VSS		VSS		VSS		VSS	BA	
BB	VDD		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		BB	
BC		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BC	
BD	VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		BD	
BE		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BE	
BF	VDD		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		BF	
BG		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BG	
BH	VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		BH	
BJ		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BJ	
BK	VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		BK	
BL		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BL	
BM	VDD		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		BM	
BN		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD	BN	
BP	VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		VDD		BP	

Figure 5-12 BE-S1000 pin map (section E)

5.2.6.6 Section F

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24		
BR		PCE2_TX_DP[6]		VSS		PCE4_RX_DN[15]		VSS		PCE2_RX_DP[10]		VSS		PCE2_ATT_IBU[1]		VSS		VDD_PCE_2_VPH		VDD_PCE_2_VP		VDD		VDD	BR	
BT	PCE2_TX_DP[9]		PCE2_TX_DN[8]		PCE4_RX_DN[14]		PCE4_RX_DP[15]		PCE2_RX_DP[11]		PCE2_RX_DN[10]		VDDIO		PCE2_MR_LSENS[1]		VDD_PCE_2_VPH		VSS		VDD_PCE_2_VP		PCE2_RE_SREF		BT	
BU		PCE2_TX_DN[9]		VSS		PCE4_RX_DP[14]		VSS		PCE2_RX_DN[11]		VSS		PCE2_ATT_IBU[2]		VSS		VDD_PCE_2_VPH		VDD_PCE_2_VP		VDD		VDD	BU	
BV	VSS		VSS		VSS		VSS		VSS		VSS		VSSIO		VSSIO		VSS_PCE_2_VPH		VSS		VDD_PCE_2_VP		VSS		BV	
BW		PCE2_TX_DP[10]		VSS		PCE4_RX_DN[13]		VSS		PCE2_RX_DP[12]		VSS		PCE2_INT_RL_ENG[0]		VSS		VDD_PCE_2_VPH		VDD_PCE_2_VP		VDD		VDD	BW	
BY	PCE2_TX_DP[11]		PCE2_TX_DN[10]		PCE4_RX_DN[12]		PCE4_RX_DP[13]		PCE2_RX_DP[13]		PCE2_RX_DN[12]		PCE2_ATT_IBU[0]		PCE2_INT_RL_ENG[1]		VSS		VSS		VDD_PCE_2_VP		VSS		BY	
CA		PCE2_TX_DN[11]		VSS		PCE4_RX_DP[12]		VSS		PCE2_RX_DN[13]		VSS		VSS		VSS		VSS		VSS		VDD		VDD	CA	
CB	VSS		VSS		VSS		VSS		VSS		VSS		PCE2_INT_RL_CTRL[0]		VSS		VSS		VSS		VSS		VSS		CB	
CC		PCE2_TX_DP[12]		VSS		PCE4_RX_DN[11]		VSS		PCE2_RX_DP[14]		VSS		VDDIO		VSS		VSS		VDD_PCE_4_VP		VDD		VDD	CC	
CD	PCE2_TX_DP[13]		PCE2_TX_DN[12]		PCE4_RX_DN[10]		PCE4_RX_DP[11]		PCE2_RX_DP[15]		PCE2_RX_DN[14]		PCE2_INT_RL_CTRL[1]		VSS		VSS		VSS		VDD_PCE_4_VP		VSS		CD	
CE		PCE2_TX_DN[13]		VSS		PCE4_RX_DP[10]		VSS		PCE2_RX_DN[15]		VSS		PCE2_CM_0_INT[1]		VSS		VDD_PCE_4_VPH		VDD_PCE_4_VP		VDD		VDD	CE	
CF	VSS		VSS		VSS		VSS		VSS		VSS		VSSIO		VSS		VDD_PCE_4_VPH		VSS		VDD_PCE_4_VP		VSS		CF	
CG		PCE2_TX_DP[14]		VSS		PCE4_RX_DN[9]		VSS		PCE2_CLK_0_DP		VSS		PCE2_PE_RST_N[0]		VSS		VDD_PCE_4_VPH		VDD_PCE_4_VP		VDD		CG		
CH	PCE2_TX_DP[15]		PCE2_TX_DN[14]		PCE4_RX_DN[8]		PCE4_RX_DP[9]		PCE2_CLK_1_DP		PCE2_CLK_0_DP		PCE2_CM_0_INT[0]		PCE2_PE_RST_N[1]		VDD_PCE_4_VPH		VSS		VDD_PCE_4_VP		VSS		CH	
CJ		PCE2_TX_DN[15]		VSS		PCE4_RX_DP[8]		VSS		PCE2_CLK_1_DN		VSS		VSS		VSS		VDD_PCE_4_VPH		VDD_PCE_4_VP		VDD		CJ		
CK	VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VDD_PCE_4_VP		VSS		CK	
CL		PCE4_TX_DN[10]		VSS		PCE4_RX_DN[7]		VSS		PCE2_CLK_2_DP		VSS		VSS		VSS		VSS		VDD_PCE_4_VP		VDD		CL		
CM	PCE4_TX_DN[14]		PCE4_TX_DP[15]		PCE4_RX_DN[6]		PCE4_RX_DP[7]		PCE2_CLK_3_DP		PCE2_CLK_2_DN		PCE4_PW_R_IND[0]		VSSIO		PCE4_PW_R_IND[2]		VSS		VSS		VSS		CM	
CN		PCE4_TX_DP[14]		VSS		PCE4_RX_DP[6]		VSS		PCE2_CLK_3_DN		VSS		PCE4_PW_R_IND[1]		PCE4_PW_R_IND[0]		VSS		VSS		VDD		VDD	CN	
CP	VSS		VSS		VSS		VSS		VSS		VSS		PCE4_PW_R_CTRL[0]		VDDIO		PCE4_PW_R_CTRL[2]		PCE4_PW_R_IND[3]		VSS		VSS		CP	
CR		PCE4_TX_DN[13]		VSS		PCE4_RX_DN[5]		VSS		VSS		VSS		PCE4_PW_R_FAULT[0]		PCE4_PW_R_FAULT[1]		PCE4_PW_R_IND[5]		VSS		VSS		VDD	CR	
CT	PCE4_TX_DN[12]		PCE4_TX_DP[13]		PCE4_RX_DN[4]		PCE4_RX_DP[5]		VSS		VSS		PCE4_PR_RST_N[0]		PCE4_PW_R_IND[1]		PCE4_PR_RST_N[2]		PCE4_PW_R_CTRL[0]		VSS		VSS		PCE4_RE_SREF	CT
CU		PCE4_TX_DP[12]		VSS		PCE4_RX_DP[4]		VSS		PCE4_CLK_0_DP		VSS		PCE4_PR_ES_ST[0]		PCE4_PR_ES_ST[1]		PCE4_PW_R_FAULT[2]		PCE4_PW_R_IND[4]		VSS		VDD	CU	
CV	VSS		VSS		VSS		VSS		PCE4_CLK_1_DP		PCE4_CLK_0_DN		VSSIO		PCE4_PW_R_CTRL[1]		VSSIO		VSS		VSS		VSS		CV	
CW		PCE4_TX_DN[11]		VSS		PCE4_RX_DN[3]		VSS		PCE4_CLK_1_DN		VSS		PCE4_MR_LSENS[0]		PCE4_MR_LSENS[1]		PCE4_PR_ES_ST[2]		PCE4_PW_R_FAULT[3]		VSS		VDD	CW	
CY	PCE4_TX_DN[10]		PCE4_TX_DP[11]		PCE4_RX_DN[2]		PCE4_RX_DP[3]		VSS		VSS		PCE4_INT_RL_ENG[0]		PCE4_PE_RST_N[1]		VDDIO		PCE4_PE_RST_N[3]		VSS		VSS		CY	

Figure 5-13 BE-S1000 pin map (section F)

5.2.6.7 Section G

	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80	
BR	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	BR							
BT	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	BT						
BU	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	BU							
BV	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	BV							
BW	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	BW							
BY	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	BY						
CA	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	CA							
CB	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	CB							
CC	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	CC							
CD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	CD							
CE	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	VDD	CE							
CF	VDD	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	VSS	CF						
CG	VDD_PCE1_1_VP	VDD_PCE1_1_VP	VSS	CG																					
CH	VDD	VDD_PCE1_1_VP	VDD_PCE1_1_VP	VDD_PCE1_1_VP	VDD_PCE1_1_VP	CS_TCK	CS_TDO	CS_TMS	VSS	CH															
CJ	PCE1_RE_SREF	VDD_PCE1_1_VP	VSS	VDDIO	CS_TRST_N	CS_TDI	VSSIO	PCE1_CLK_3_DN	PCE1_RX_DN[14]	PCE1_TX_DP[15]	CJ														
CK	VDD	SMB0_ALE_RT	VDDIO	VDDIO	GO_TX_DAT[0]	GO_TX_DAT[2]	GO_MDI0	PCE1_CLK_2_DN	PCE1_CLK_3_DP	PCE1_RX_DP[14]	VSS	CK													
CL	VSS	SMB0_A	VDDIO	VDDIO	GO_TX_CLK	GO_TX_DAT[1]	GO_TX_DAT[3]	VSSIO	PCE1_CLK_2_DP	VSS	CL														
CM	VSS	SMB0_CLK	RESET_N	VDDIO	GO_TX_DE_N	VDDIO	GO_MDC	VSS	CM																
CN	REFCLK	VDDIO	VDDIO	GO_RX_CLK	GO_RX_DA_T[1]	GO_RX_DA_T[3]	VSSIO	PCE1_CLK_1_DN	PCE1_RX_DN[13]	PCE1_RX_DP[13]	VSS	CN													
CP	VSS	SMB0_SUS_IN	USB2_DAT[0]	USB2_DIR	GO_RX_DA_T[0]	GO_RX_DA_T[2]	GO_GP_IN	PCE1_CLK_0_DN	PCE1_CLK_1_DP	PCE1_RX_DP[12]	VSS	CP													
CR	REFCLK_SEL	VDDIO	USB2_CLK	GO_RX_DE_N	VDDIO	GO_GP_OUT	VSSIO	PCE1_CLK_0_DP	VSS	CR															
CT	VSS	SMB0_SUS_OUT	USB2_DAT[1]	USB2_NXT	G1_TX_DAT[0]	G1_TX_DAT[2]	G1_MDI0	VSS	CT																
CU	VSS	BOOT_MODE	USB2_DAT[5]	G1_TX_CLK	G1_TX_DAT[1]	G1_TX_DAT[3]	VSSIO	VSS	VSS	PCE1_RX_DN[10]	PCE1_RX_DP[11]	PCE1_TX_DN[10]	PCE1_TX_DP[11]	CU											
CV	VDD	VSS	USB2_DAT[2]	VSSIO	G1_TX_DE_N	VDDIO	G1_MDC	VSS	CV																
CW	VSS	VSSIO	USB2_DAT[3]	USB2_STP	G1_RX_CLK	G1_RX_DA_T[0]	G1_RX_DA_T[3]	VDD_PCE1_1_VPH	DDR0_DQ[4]	VSS	CW														
CY	VDD	VSSIO	USB2_DAT[3]	USB2_STP	G1_RX_DA_T[0]	G1_RX_DA_T[2]	G1_GP_IN	DDR0_DQ[5]	VSS	CY															

Figure 5-14 BE-S1000 pin map (section G)

5.2.6.8 Section H

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24				
DA		PCIE4_TX_DP[16]		VSS		PCIE4_RX_DP[2]		VSS		PCIE4_CLK_2_DP		VSS		VDDO		VSSIO		PCIE4_MR_L_SEN[2]		PCIE4_MR_ES_3[3]		VSS		VDD	DA			
DB	VSS		VSS		VSS		VSS		PCIE4_CLK_3_DP		PCIE4_CLK_2_DN		PCIE4_CM_D_INT[3]		PCIE4_INT_RL_EN[2]		PCIE4_INT_RL_EN[3]		PCIE4_INT_RL_EN[3]		VSS		VSS		VSS	DB		
DC		PCIE4_TX_DN[8]		VSS		PCIE4_RX_DN[1]		VSS		PCIE4_CLK_3_DN		VSS		PCIE4_INT_RL_CTRL[3]		PCIE4_INT_RL_CTRL[1]		PCIE4_INT_RL_CTRL[2]		PCIE4_MR_L_SEN[3]		VSS		VSS	DC			
DD	PCIE4_TX_DN[5]		PCIE4_TX_DP[5]		PCIE4_RX_DN[3]		PCIE4_RX_DP[1]		VSS		VSS		PCIE4_ATT_IND[3]		PCIE4_CM_D_INT[3]		PCIE4_CM_D_INT[3]		PCIE4_CM_D_INT[3]		VSS		VSS		VSS	DD		
DE		PCIE4_TX_DP[8]		VSS		PCIE4_RX_DP[3]		VSS		VSS		VSS		PCIE4_ATT_IND[5]		PCIE4_ATT_IND[5]		PCIE4_ATT_IND[4]		PCIE4_INT_RL_CTRL[3]		VSS		VSS	DE			
DF	VSS		VSS		VSS		VSS		VSS		VSS		PCIE4_ATT_IND[7]		PCIE4_ATT_IND[1]		PCIE4_ATT_IND[2]		PCIE4_ATT_IND[3]		VSS		VSS		VSS	DF		
DG		PCIE4_TX_DN[7]		VSS		VSS		VSS		VSS		VSS		PCIE4_ATT_IND[1]		PCIE4_ATT_IND[3]		PCIE4_ATT_IND[7]		VSS		VSS		VSS	DG			
DH	PCIE4_TX_DN[6]		PCIE4_TX_DP[7]		DDR3_DQ[58]		DDR3_DQ[59]		DDR3_DQS_DN[15]		DDR3_DQ[48]		VSS		PCIE4_ATT_IND[2]		VSSIO		VSS		VSS		VSS		VSS	DH		
DJ		PCIE4_TX_DP[6]		VSS		DDR3_DQ[58]		DDR3_DQ[54]		DDR3_DQS_DN[19]		DDR3_DQ[52]		VSS		VSS		VSS		VSS		VSS		VSS		VSS	DJ	
DK	VSS		VSS		DDR3_DQ[63]		DDR3_DQ[51]		DDR3_DQS_DP[8]		DDR3_DQ[49]		VSS		VDDQ348		VDDQ346		VDDQ346		VDDQ346		VDDQ346		VDDQ346	DK		
DL		PCIE4_TX_DN[5]		VSS		DDR3_DQ[62]		DDR3_DQ[55]		DDR3_DQS_DN[9]		DDR3_DQ[53]		VSS		VSS		VSS		VSS		VSS		VSS		VSS	DL	
DM	PCIE4_TX_DN[4]		PCIE4_TX_DP[5]		VSS		VSS		VSS		VSS		VSS		VSS		DDR3_ODT[2]		DDR3_BA[1]		DDR3_CLK_DP[2]		DDR3_A[8]		VSS	DM		
DN		PCIE4_TX_DP[4]		VSS		DDR3_DQS_DP[7]		DDR3_DQ[46]		DDR3_DQS_DP[16]		DDR3_DQ[44]		VSS		DDR3_ODT[1]		DDR3_CS_N[3]		DDR3_CLK_DN[6]		DDR3_A[2]		DDR3_A[11]		VSS	DN	
DP	VSS		VSS		DDR3_DQS_DN[7]		DDR3_DQ[42]		DDR3_DQS_DN[14]		DDR3_DQ[40]		VSS		DDR3_ODT[8]		DDR3_A[10]		DDR3_CLK_DP[2]		DDR3_A[3]		DDR3_A[9]		VSS	DP		
DR		PCIE4_TX_DN[3]		VSS		DDR3_DQS_DN[18]		DDR3_DQ[47]		DDR3_DQS_DN[5]		DDR3_DQ[45]		VSS				DDR3_A[14]		DDR3_CLK_DN[2]		DDR3_A[11]		DDR3_A[10]		VSS	DR	
DT	PCIE4_TX_DN[2]		PCIE4_TX_DP[3]		DDR3_DQS_DP[16]		DDR3_DQ[43]		DDR3_DQS_DP[5]		DDR3_DQ[41]		VSS		VDDQ348		VDDQ346		VDDQ346		VDDQ346		VDDQ346		VDDQ346		VSS	DT
DU		PCIE4_TX_DP[2]		VSS		VSS		VSS		VSS		VSS		DDR3_CS_N[2]		DDR3_CS_N[1]		DDR3_BA[0]		DDR3_CLK_DN[2]		DDR3_A[8]		DDR3_B[0]		VSS	DU	
DV	VSS		VSS		DDR3_DQ[57]		DDR3_DQ[34]		DDR3_DQS_DN[16]		DDR3_DQ[32]		VSS		DDR3_ODT[6]		DDR3_A[15]		DDR3_PAR		DDR3_CLK_DP[1]		DDR3_A[7]		VSS	DV		
DW		PCIE4_TX_DN[1]		VSS		DDR3_DQ[56]		DDR3_DQ[38]		DDR3_DQS_DP[13]		DDR3_DQ[36]		DDR3_CS_N[3]		DDR3_A[17]		DDR3_A[16]		DDR3_CLK_DN[3]		DDR3_A[4]		DDR3_A[3]		VSS	DW	
DY	PCIE4_TX_DN[3]		PCIE4_TX_DP[4]		DDR3_DQ[40]		DDR3_DQ[32]		DDR3_DQS_DP[4]		DDR3_DQ[30]		VSS				DDR3_A[13]		DDR3_A[5]		DDR3_CLK_DP[3]		DDR3_A[9]		VSS	DY		
EA		PCIE4_TX_DP[0]		VSS		DDR3_DQ[60]		DDR3_DQ[38]		DDR3_DQS_DN[4]		DDR3_DQ[37]		VDDQ348		VDDQ346		VDDQ346		VDDQ346		VDDQ346		VDDQ346		VSS	EA	
EB	VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS	EB		
EC		VSS		DDR4_DQ[63]		VSS		VSS		VSS		VSS		VSS		VSS		DDR4_DQS_DP[5]		DDR4_DQ[41]		VSS		DDR4_DQS_DN[13]		VSS	EC	
ED	VSS		DDR4_DQ[55]		VSS		DDR4_DQ[57]		VSS		DDR4_DQ[51]		VSS		DDR4_DQ[52]		DDR4_DQ[42]		DDR4_DQS_DN[5]		DDR4_DQ[44]		DDR4_DQ[39]		VSS	ED		
EE		VSS		DDR4_DQ[52]		DDR4_DQS_DN[7]		DDR4_DQ[51]		DDR4_DQ[51]		DDR4_DQS_DN[15]		DDR4_DQ[45]		VSS		VSS		VSS		VSS		VSS		VSS	EE	
EF			DDR4_DQ[58]		DDR4_DQS_DP[7]		DDR4_DQ[56]		VSS		DDR4_DQ[54]		DDR4_DQS_DP[15]		DDR4_DQ[53]		DDR4_DQ[47]		VSS		DDR4_DQ[45]		DDR4_DQ[34]		VSS	EF		
EG			VSS		DDR4_DQS_DP[16]		DDR4_DQ[60]		DDR4_DQ[50]		DDR4_DQS_DP[9]		DDR4_DQ[46]		VSS		DDR4_DQ[46]		DDR4_DQS_DP[14]		VSS		VSS		DDR4_DQ[36]	EG		
EH					DDR4_DQS_DN[16]		VSS		VSS		VSS		DDR4_DQS_DN[6]		VSS		DDR4_DQ[43]		DDR4_DQS_DN[14]		DDR4_DQ[40]		DDR4_DQ[35]		VSS	EH		

Figure 5-15 BE-S1000 pin map (section H)

5.2.6.10 Section J

	57	58	59	60	61	62	63	64	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80	
DA				WDT_RESET		USB2_DAT[7]		GPIO_XDE_N		VDDIO		GPIO_OUT		VDD_PCE_L_VPH		DDR5_DQ[0]		PCIE1_RX_DN[8]		PCIE1_RX_DP[9]		PCIE1_TX_DN[6]		PCIE1_TX_DP[9]	DA
DB	VSS		SPI0_TBAI_A/DFF		USB2_DAT[4]		USB2_CFG		UART0_TX_D		VDDIO		VDD_PCE_L_VPH		DDR5_DQ[1]		VSS		PCIE1_RX_DP[8]		VSS		PCIE1_TX_DP[8]	DB	
DC		SMB1_SUB_OUT		VSS		GPIO0_A2		VSSIO		UART0_RX_D		VDD_PCE_L_VPH		VDD_PCE_L_VPH		DDR5_DQS_DP[9]		VSS		VSS		VSS		VSS	DC
DD			VSSIO		GPIO0_A1		VDDIO		VSSIO		VSSIO		DDR5_DQ[2]		DDR5_DQS_DP[9]		VSS		PCIE1_RX_DN[7]		VSS		PCIE1_TX_DN[7]	DD	
DE		SMB1_SUB_N		GPIO0_A0		GPIO0_A3		GPIO0_A5		VSSIO		VSS		VSS		DDR5_DQS_DN[9]		PCIE1_RX_DN[6]		PCIE1_RX_DP[7]		PCIE1_TX_DN[6]		PCIE1_TX_DP[7]	DE
DF	VSS		VDDIO		VSSIO	GPIO0_A4		GPIO0_A7		VSS		DDR5_DQ[3]		DDR5_DQS_DP[9]		VSS		PCIE1_RX_DP[6]		VSS		PCIE1_TX_DP[6]	DF		
DG		SMB1_DAT_A		SPI0_TQD		SPI0_RXD		GPIO0_A6		VDDIO		VSS		VSS		VSS		VSS		VSS		VSS		VSS	DG
DH	VSS		SMB1_ALE_RT		SPI0_CLK		SPI0_SS_N[3]		VSSIO		DDR5_DQ[18]		DDR5_DQS_DP[11]		DDR5_DQ[16]		DDR5_DQ[6]		PCIE1_RX_DN[9]		VSS		PCIE1_TX_DN[9]	DH	
DJ		SMB1_CLK		VSSIO		VSS		SPI0_SS_N[1]		VSS		DDR5_DQ[22]		DDR5_DQS_DP[11]		DDR5_DQ[7]		VSS		PCIE1_RX_DP[9]		PCIE1_TX_DN[4]		PCIE1_TX_DP[9]	DJ
DK	VDDQ345		VDDQ345		VDDQ345		VDDQ345		VSS		DDR5_DQ[19]		DDR5_DQS_DP[2]		DDR5_DQ[17]		DDR5_DQ[2]		PCIE1_RX_DN[4]		VSS		PCIE1_TX_DN[4]	DK	
DL		VSS		VSS		VSS		VSS		VSS	DDR5_DQ[23]		DDR5_DQS_DP[3]		DDR5_DQ[3]		VSS		PCIE1_RX_DP[8]		VSS		VSS	DL	
DM	DDR5_BA[1]		DDR5_CLK_DP[1]		DDR5_A[8]		DDR5_ALE_RT_N		VSS		VSS		VSS		VSS		VSS		PCIE1_RX_DN[3]		VSS		PCIE1_TX_DN[3]	DM	
DN		DDR5_CLK_DN[3]		DDR5_A[2]		DDR5_A[1]		DDR5_CKE[5]		DDR5_DQ[25]		DDR5_DQS_DP[3]		DDR5_DQ[24]		DDR5_DQ[12]		VSS		PCIE1_RX_DP[3]		PCIE1_TX_DN[5]		PCIE1_TX_DP[3]	DN
DP	DDR5_A[10]		DDR5_CLK_DP[2]		DDR5_A[3]		DDR5_B[0]		VSS		DDR5_DQ[30]		DDR5_DQS_DP[12]		DDR5_DQ[28]		DDR5_DQ[13]		PCIE1_RX_DN[2]		VSS		PCIE1_TX_DP[2]	DP	
DR		DDR5_CLK_DN[2]		DDR5_A[1]		DDR5_A[12]		DDR5_CKE[1]		DDR5_DQ[27]		DDR5_DQS_DP[3]		DDR5_DQ[25]		DDR5_DQ[8]		VSS		PCIE1_RX_DP[2]		VSS		VSS	DR
DT	VDDQ345		VDDQ345		VDDQ345		VDDQ345		VSS		DDR5_DQ[31]		DDR5_DQS_DP[12]		DDR5_DQ[26]		DDR5_DQ[9]		VSS		PCIE1_RX_DN[1]		PCIE1_TX_DN[1]	DT	
DU		DDR5_CLK_DN[1]		DDR5_A[8]		DDR5_B[1]		DDR5_CKE[3]		VSS		VSS		VSS		VSS		VSS		VSS		VSS		PCIE1_TX_DP[1]	DU
DV	DDR5_PAR		DDR5_CLK_DP[1]		DDR5_A[7]		DDR5_CKE[8]		VSS		DDR5_ECC[6]		DDR5_DQS_DP[17]		DDR5_ECC[4]		DDR5_DQ[14]		DDR5_DQS_DP[13]		PCIE1_RX_DP[11]		PCIE1_TX_DN[2]	DV	
DW		DDR5_CLK_DN[3]		DDR5_A[6]		DDR5_A[16]		DDR5_RESET_N		DDR5_ECC[2]		DDR5_DQS_DP[17]		DDR5_ECC[0]		DDR5_DQ[10]		DDR5_DQS_DP[10]		VSS		VSS		PCIE1_TX_DP[2]	DW
DY	DDR5_A[9]		DDR5_CLK_DP[3]		DDR5_A[9]		DDR5_ACT_A		VSS		DDR5_ECC[7]		DDR5_DQS_DP[6]		DDR5_ECC[5]		DDR5_DQ[15]		DDR5_DQS_DP[11]		PCIE1_RX_DN[0]		VSS	DY	
EA		VDDQ345		VDDQ345		VDDQ345		VDDQ345		DDR5_ECC[3]		DDR5_DQS_DP[8]		DDR5_ECC[1]		DDR5_DQ[11]		DDR5_DQS_DP[1]		VSS		PCIE1_RX_DP[0]		VSS	EA
EB	VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS	EB	
EC		DDR4_DQS_DN[12]		DDR4_DQ[28]		DDR4_DQ[23]		DDR4_DQS_DN[11]		DDR4_DQ[20]		DDR4_DQ[15]		DDR4_DQS_DN[10]		DDR4_DQ[12]		DDR4_DQ[7]		VSS		VSS		DDR4_DQ[4]	EC
ED	DDR4_DQ[30]		DDR4_DQS_DP[12]		VSS		DDR4_DQ[22]		DDR4_DQS_DP[11]		VSS		DDR4_DQ[14]		DDR4_DQS_DP[10]		VSS		DDR4_DQ[6]		DDR4_DQS_DP[8]		DDR4_DQ[5]	ED	
EE		VSS		DDR4_DQ[29]		DDR4_DQ[19]		VSS		DDR4_DQ[21]		DDR4_DQ[11]		VSS		DDR4_DQ[13]		DDR4_DQ[3]		DDR4_DQS_DN[9]		DDR4_DQ[0]		VSS	EE
EF	VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		VSS		DDR4_DQ[1]		VSS	EF	
EG		DDR4_DQS_DN[8]		DDR4_DQ[24]		DDR4_DQ[18]		DDR4_DQS_DN[2]		DDR4_DQ[16]		DDR4_DQ[10]		DDR4_DQS_DN[1]		DDR4_DQ[8]		DDR4_DQ[2]		DDR4_DQS_DN[0]		VSS		EG	
EH	DDR4_DQS_DP[3]		DDR4_DQ[25]		VSS		DDR4_DQS_DP[2]		DDR4_DQ[17]		VSS		DDR4_DQS_DP[1]		DDR4_DQ[9]		VSS		DDR4_DQS_DP[0]		VSS			EH	

Figure 5-17 BE-S1000 pin map (section J)

6 Package and Ordering Information

6.1 Ordering information

BE-S1000 is an orderable part number. Designation of each field in the part number is shown in a table below.

Table 6-1 Ordering information

BE	-	S	1	0	0	0	X
Baikal Electronics	Field Delimiter	Product Line	Generation	Modification	Reserved Field	Reserved Field	Corner

BE-S1000 is the first product in the BE-S product line.

To order BE-S1000, please contact BAIKAL ELECTRONICS company.

6.2 Marking

The following table shows designation of each field in the package marking of BE-S1000.

Table 6-2 BE-S1000 package marking

A	K	.	YY	WW
Type of a set of photomasks	Manufacturer of the substrate housing	Field Delimiter	Year	Week

6.3 FCLGA-3467 Package

The SoC is mounted into FCLGA-3467 package. Main package parameters are shown in the following figures.

NOTE: The package size values are represented in mm.

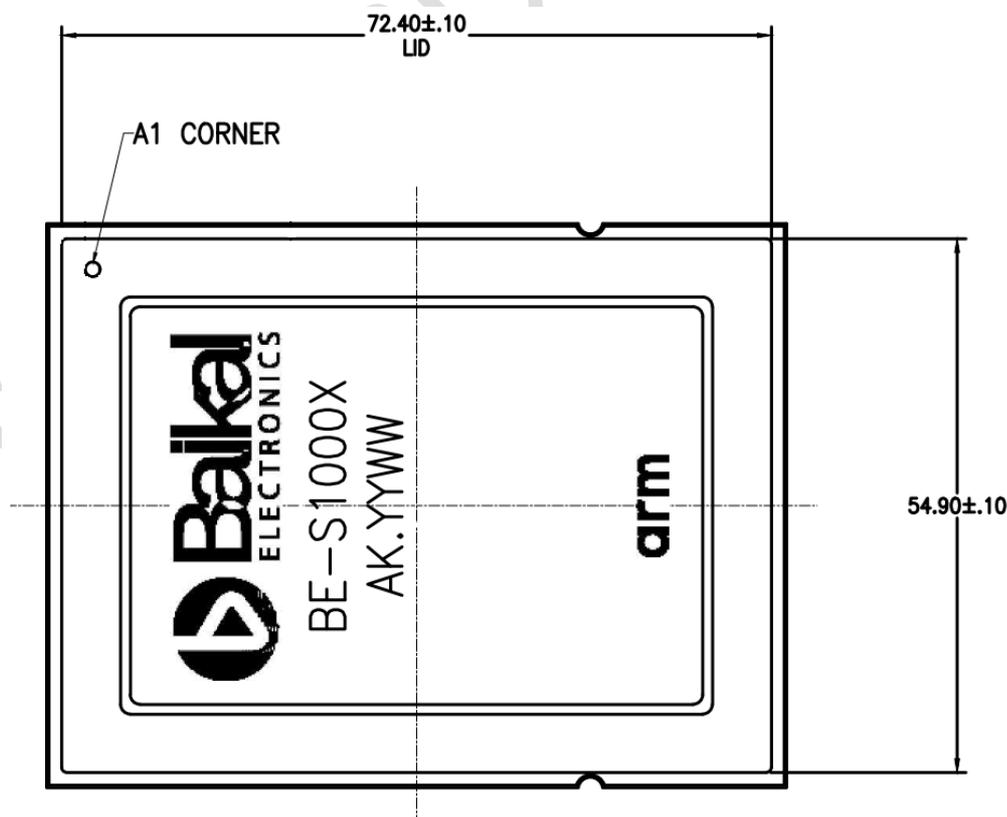


Figure 6-1 BE-S1000 package. Top view

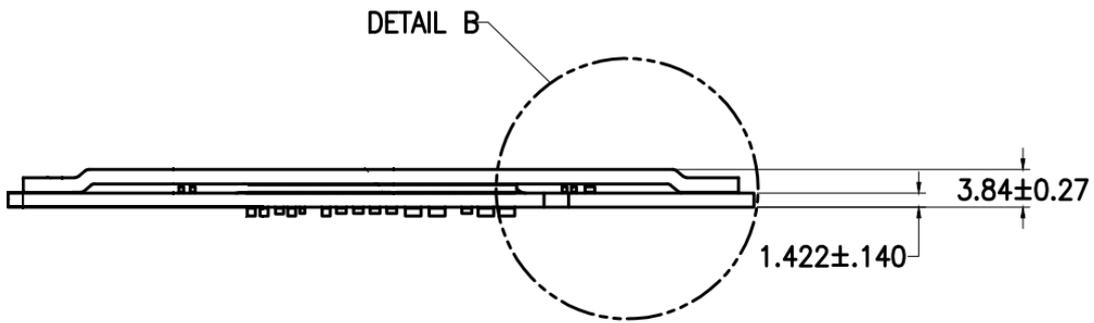


Figure 6-2 BE-S1000 package. Side view

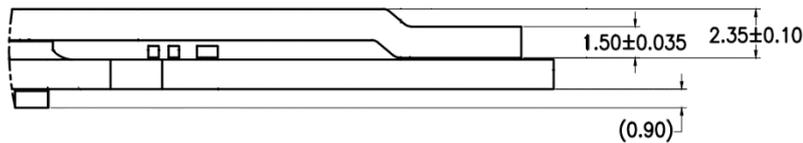


Figure 6-3 Detail B

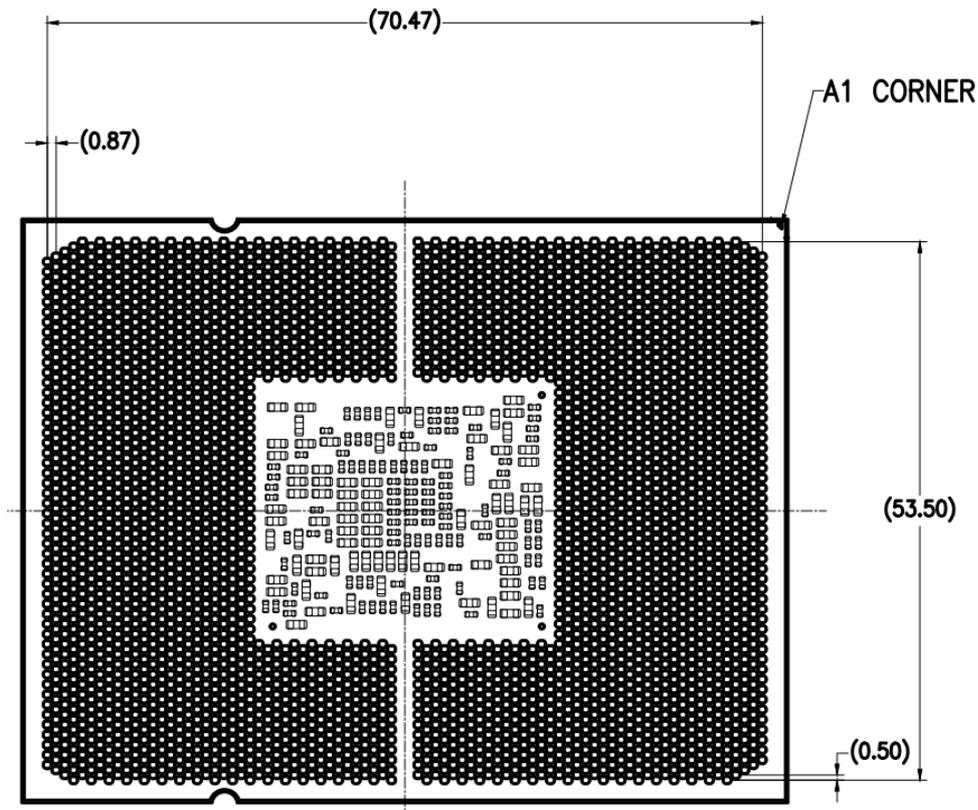


Figure 6-4 BE-S1000 package. Bottom view

6.4 Delivery Set

The following standart components are included in the delivery set:

- Socket
- Heatsink

A detailed description of each element and its packaging is given in the document *Microprocessor BE-S1000. Thermo-Mechanical Design Guide (TMDG)*.

ATTENTION: It's unacceptable to use a microprocessor without a radiator. The manufacturer isn't responsible for the performance of the microprocessor when using a non-standard radiator.

6.5 Packing

The microprocessors are supplied in plastic containers (in the amount of 1 to 6 pieces each), as shown in the following figure.

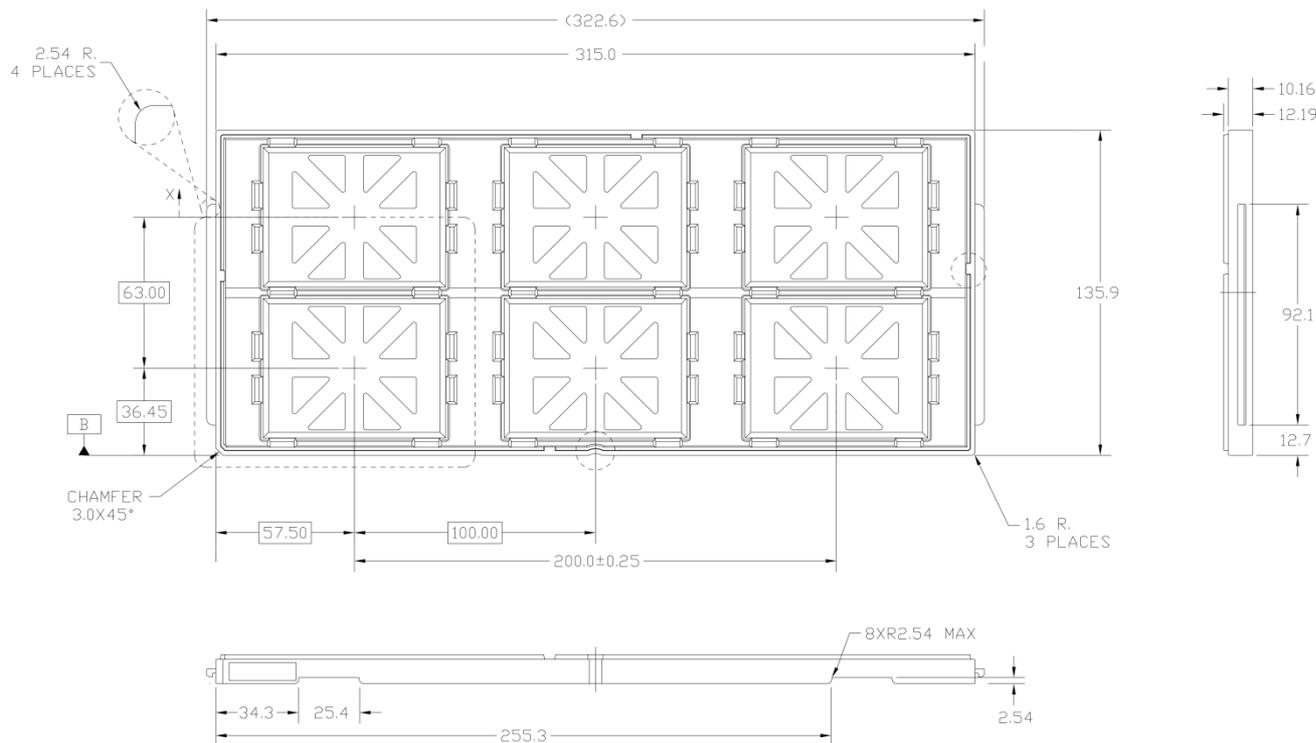


Figure 6-5 – BE-S1000 packaging

Plastic containers are placed in sealed packaging containing moisture absorption and humidity control means (indicator card). The sealed package is placed in a cardboard shipping box. The permissible time of atmospheric exposure may be indicated on sealed plastic packages.

The unused space is filled with a soft sealing material.

The space between trays is padded with a soft sealing material.

7 Support

7.1 Documentation

The following documents describe the BE-S1000 microprocessor and provide information for board designers and system programmers:

- [Power Supply Requirements](#)
- [Application Design Guide](#)
- [Thermo-Mechanical Design Guide](#)
- [Programming Guide](#)

7.1.1 Power Supply Requirements

Each power domain of BE-S1000 requires the use of special filters on the power supply. The power supply requirements are described in the document written in Russian under the title «Микропроцессор BE-S1000 Требования к источникам питания». The power supply requirements are under development and will be available in Russian only.

7.1.2 Application Design Guide

The *Application Design Guide (ADG)* describes how to design the BE-S1000 physical interfaces on a board.

ADG is under development and will be available in English only.

To request the guide, please contact BAIKAL ELECTRONICS support. **NDA is required.**

The following table describes the guide content.

Table 7-1 BE-S1000 application design guide

Volume	Title
1	DDR4
2	PCIe
3	USB 2.0
4	1 Gb Ethernet
5	eSPI
6	QSPI
7	UART
8	GPIO
9	JTAG
10	I ² C/SMBus

7.1.3 Thermo-Mechanical Design Guide

The TMDG is intended to assist board and system thermal mechanical designers, as well as designers and suppliers of processor heatsinks.

TMDG is under development in Russian only (under the title «Руководство по термомеханическому проектированию»).

7.1.4 Programming Guide

The *Programming Guide (PG)* describes how to program the microprocessor subsystems and provides information for developers of device drivers or bare-metal applications.

The following table describes the guide content.

Table 7-2 BE-S1000 programming guide

	Volume	Title
1	1	General Description
2	2	Memory Map
3	3	Interrupts
SoC Interconnects		
4	4.1	Network Interconnect (NIC)
5	4.2	Coherent Mesh Network (CMN)
System Debug		
6	5	CoreSight Subsystem
System Monitoring and Management		
7	6.1	Local Clock and Reset Unit (LCRU)
8	6.2	Process, Voltage and Temperature (PVT) Sensors
Memory Management		
9	7.1	DDR4 Memory Controller
10	7.2	DDR PHY
11	7.3	System Memory Management Unit (SMMU)
Connectivity & Mass Storage		
12	8.1	PCIe RootComplex Controller
13	8.2	PCIe Dual Mode (CCIX/RC) Controller
14	8.3	PCIe Subsystem APB Bridge
15	8.4	PCIe PHY
16	8.5	1Gb Ethernet MAC (GMAC)
17	8.6	USB 2.0 Controller
Timers		
18	9.1	Cortex-A75 Timers
19	9.2	Peripheral Timers
20	9.3	Watchdog Timer
Low Speed Peripherals		
21	10.1	I2C/System Management Bus Controller (I2C/SMBus)
22	10.2	Quad Serial Peripheral Interface (QSPI)
23	10.3	Enhanced Serial Peripheral Interface (eSPI)
24	10.4	Universal Asynchronous Receiver/Transmitter, Type «A» (UART_A)
25	10.5	Universal Asynchronous Receiver/Transmitter, Type «S» (UART_S)
26	10.6	General Purpose Input/Output (GPIO)

PG is under development and will be available in English only.

To request the guide, please contact BAIKAL ELECTRONICS support. **NDA is required.**

7.2 SDK

BAIKAL ELECTRONICS produces the *Software Development Kit (SDK)* ARM64, which provides software support for the BE-S1000 microprocessor.

To provide your application compatibility with the SDK ARM64, you should follow the requirements described in the document written in Russian under the title «Базовый набор требований и рекомендаций по построению аппаратных платформ на базе СнК (SoC) BE-S1000» that is under development.

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Preliminary Datasheet

Revision History

Revision	Date	Substantive change(s)
0.30	December 13, 2021	Initial version
0.33	March 17, 2022	Added: <ul style="list-style-type: none">• Ordering Information• Supported ISAs in Arm Cortex-A75 CPU Cluster
0.35	July 05, 2022	Added: <ul style="list-style-type: none">• Packing• Delivery Set• Marking• SDK• Power Supply Requirements• Figure 4-1 Start Sequence Diagram for the BE-S1000
0.37	January 16, 2023	Minor edits

Preliminary Datasheet